



HY17P60B

Datasheet

8-Bit RISC-like Mixed Signal Microcontroller
Embedded 19-Bit $\Sigma\Delta$ ADC
With Low Noise OPAMP & 4x20 LCD

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Embedded 19-Bit $\Sigma\Delta$ ADC with LNA OPAMP & 4x20 LCD

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1. 特点

- 8bit 加强型精简指令集，共有 71 个指令
包含硬件乘法指令及查表指令 H08D，支持 C Compiler 编译环境
- 数字电路工作电压范围 2.2V to 5.5V，
模拟电路工作电压范围 2.4V to 4.5V，
工作温度范围-40~85°C
- 8k Word OTP (One Time Programmable)
程序内存，512Byte 数据存储器
- 高分辨率 $\Sigma\Delta$ ADC
 - 最高取样频率达 1MHz
 - 超取样频率设置 32~61440
 - 二/三阶梳状滤波器，转换频率 30.72ksps
 - 信号放大 x1/2, x1,x2,x4,x8
 - 零输入电压，零输出电压
 - 高输入阻抗 (内置输入缓冲器)
 - 内置绝对温度传感器
- 内建数字讯号处理(DSP)实现数字 AC 有效值计算功能
- 多功能比较器
 - 可实现 LVD 低电压检测功能具多段检测电压设置与外部输入电压检测功能
 - 具有迟滞与 latch 功能，可降低 glitch
- 运算放大器
 - 搭配外部组件实现 AC 整流滤波电路
- 模拟电压源 VDDA 具 10mA 稳压电压源输出，快速启动功能
- 通用型 I/O
 - HY17P60B：最多支持 26 支 I/O 管脚
- 1.2V 的内部模拟电路共地电压源
- 4x20 LCD 液晶驱动器
 - 1/4 Duty、1/3 Bias
 - 内建 Charge Pump 稳压线路，可提供多种 LCD 偏压
 - 2 个 LCD 端口可设定数字输入输出端口
- 3 组 24 bits 可程序化计数器可同时量测频率，周期与占空比
- 8-bit Timer A1
- 16-bit Timer B 模块具 PWM 功能
- UART 模块
- I²C 通信(支持 Master 及 Slave 模式)模块
- Built-In EPROM (BIE)，内建 2.75V 低压烧录控制电路
- 内建 Brownout 与 Watch dog timer，可防止 CPU 进入死机模式
- 支持外部石英震荡器 1MHz~16MHz /32768HZ 及内部高精度 RC 震荡器 4.9152MHz/9.8304MHz Mode 多种 CPU 工作频率切换选择，可让使用者达到最佳省电规划
 - 运行模式
 - 待机模式: LPO 14.5kHz
 - 休眠模式
- Support 8 stack level
- 封装
 - LQFP64、QFN32
- 应用领域
 - 2000 Counts DMM、量测仪器
 - 红外测温、计量仪器

HY17P60B

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Embedded 19-Bit $\Sigma\Delta$ ADC with LNA OPAMP & 4x20 LCD

2. 引脚图

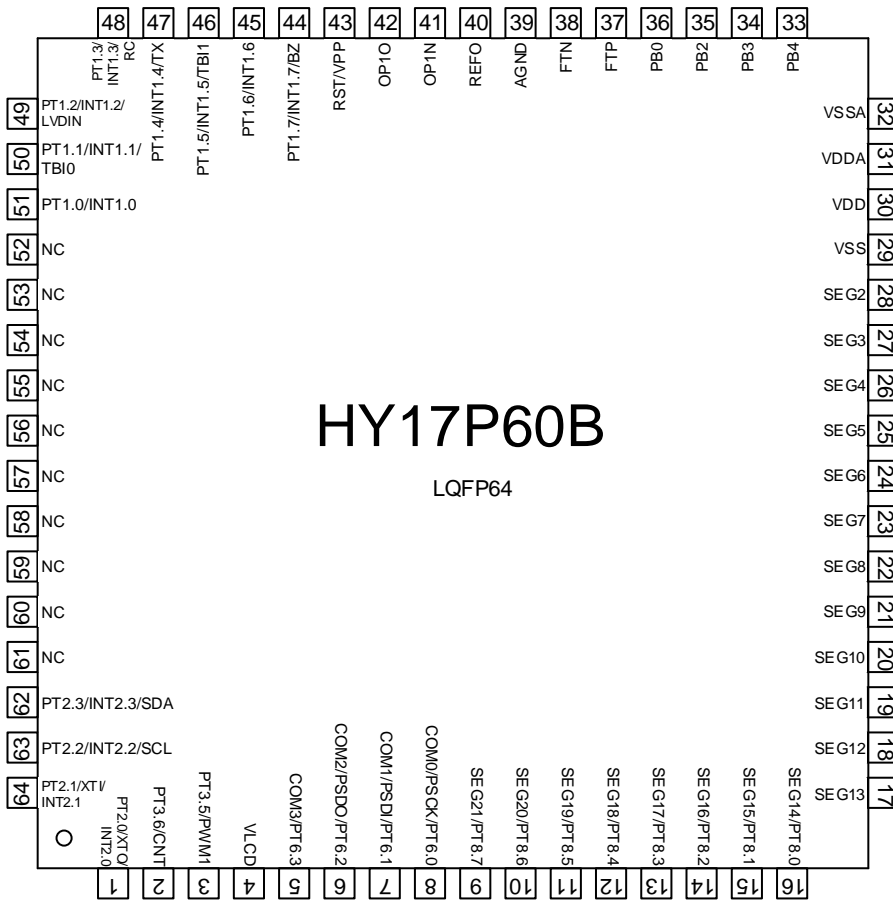


图 2-1 引脚图 HY17P60B LQFP64

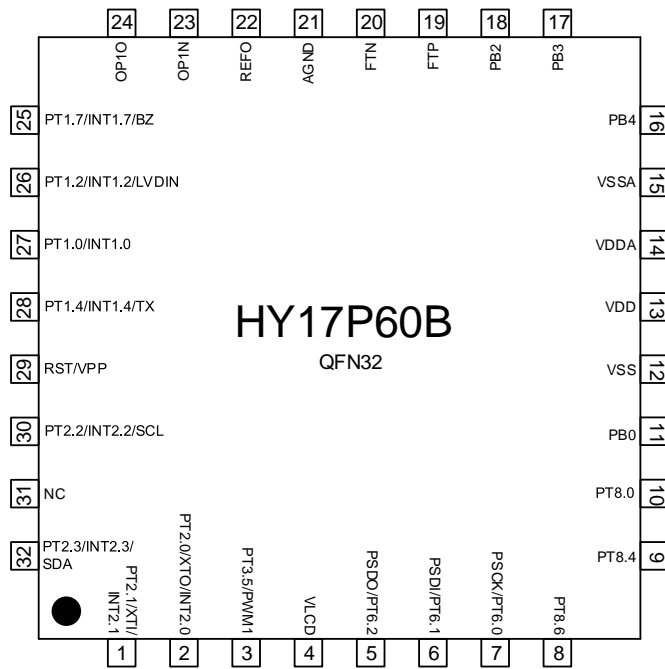


图 2-2 引脚图 HY17P60B QFN32

2.1. HY17P60B 引脚定义说明

“I/O”输入/输出,“I”输入,“O”输出,“S”史密斯触发,“C”CMOS 特性兼容输出与输入,“P”电压源,“A”模拟通道

封装 / 编号 / 脚位		设计			功能说明	
LQFP64	QFN32	名称/功能	型式	缓冲		
1	2	PT2.0/XTO/INT2.0				通用 I/O 口 外接振荡器输出端 中断源 INTF2.0
		PT2.0	I/O	S/C		
		XTO	A	A		
		INT2.0	I	S		
2	-	PT3.6/CNT				通用 I/O 口 频率计数输入接口
		PT3.6	I/O	S/C		
		CNT	I	S		
3	3	PT3.5/PWM1				通用 I/O 口 PWM1 输出接口
		PT3.5	I/O	S/C		
		PWM1	O	C		
4	4	VLCD				LCD 的电压源, BIE 倍压电压源 1~10uF need. (Source: VDD)
5	-	COM3/PT6.3				LCD Common 3 驱动输出 通用 I/O 口
		COM3	O	A		
		PT6.3	I/O	S/C		
6	5	COM2/PSDO/PT6.2				LCD Common 2 驱动输出 OTP 读/写界面接口 通用 I/O 口
		COM2	O	A		
		PSDO	O	S		
		PT6.2	I/O	S/C		
7	6	COM1/PSDI/PT6.1				LCD Common 1 驱动输出 OTP 读/写界面接口 通用 I/O 口
		COM1	O	A		
		PSDI	I	S		
		PT6.1	I/O	S/C		
8	7	COM0/PSCK/PT6.0				LCD Common 0 驱动输出 OTP 读/写界面接口 通用 I/O 口
		COM0	O	A		
		PSCK	I	S		
		PT6.0	I/O	S/C		
9	-	SEG21/PT8.7				LCD Segment 21 驱动输出 通用 I/O 口
		SEG21	O	A		
		PT8.7	I/O	S/C		

封装 / 编号 / 脚位		设计			功能说明
LQFP64	QFN32	名称/功能	型式	缓冲	
10	8	SEG20/PT8.6 SEG20 PT8.6	O I/O	A S/C	LCD Segment 20 驱动输出 通用 I/O 口
11	-	SEG19/PT8.5 SEG19 PT8.5	O I/O	A S/C	LCD Segment 19 驱动输出 通用 I/O 口
12	9	SEG18/PT8.4 SEG18 PT8.4	O I/O	A S/C	LCD Segment 18 驱动输出 通用 I/O 口
13	-	SEG17/PT8.3 SEG17 PT8.3	O I/O	A S/C	LCD Segment 17 驱动输出 通用 I/O 口
14	-	SEG16/PT8.2 SEG16 PT8.2	O I/O	A S/C	LCD Segment 16 驱动输出 通用 I/O 口
15	-	SEG15/PT8.1 SEG15 PT8.1	O I/O	A S/C	LCD Segment 15 驱动输出 通用 I/O 口
16	10	SEG14/PT8.0 SEG14 PT8.0	O I/O	A S/C	LCD Segment 14 驱动输出 通用 I/O 口
17	-	SEG13	O	A	LCD Segment 13 驱动输出
18	-	SEG12	O	A	LCD Segment 12 驱动输出
19	-	SEG11	O	A	LCD Segment 11 驱动输出
20	-	SEG10	O	A	LCD Segment 10 驱动输出
21	-	SEG9	O	A	LCD Segment 9 驱动输出
22	-	SEG8	O	A	LCD Segment 8 驱动输出
23	-	SEG7	O	A	LCD Segment 7 驱动输出
24	-	SEG6	O	A	LCD Segment 6 驱动输出
25	-	SEG5	O	A	LCD Segment 5 驱动输出
26	-	SEG4	O	A	LCD Segment 4 驱动输出
27	-	SEG3	O	A	LCD Segment 3 驱动输出
28	-	SEG2	O	A	LCD Segment 2 驱动输出
29	12	VSS	P	P	芯片工作电压源接地端
30	13	VDD	P	P	芯片工作电压源, 1~10uF need.

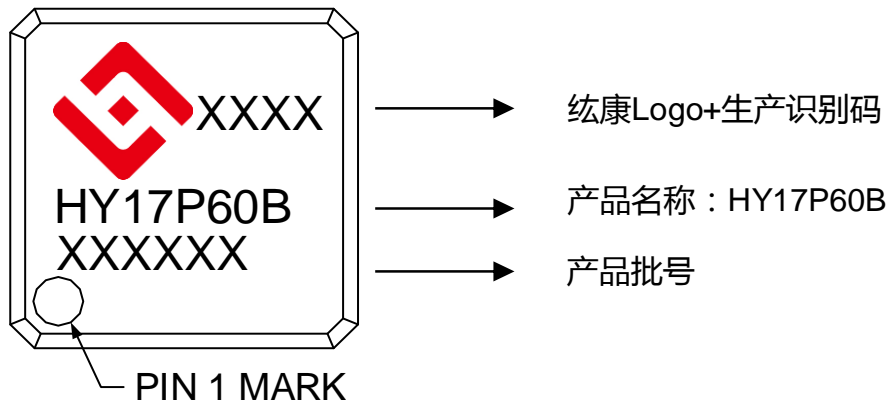
封装 / 编号 / 脚位		设计			功能说明
LQFP64	QFN32	名称/功能	型式	缓冲	
31	14	VDDA	P	P	稳压器输出, 模拟电路电压源 (source: VDD)
32	15	VSSA	P	P	芯片工作电压源接地端
33	16	PB4	I	A	模拟输入通道
34	17	PB3	I	A	模拟输入通道
35	18	PB2	I	A	模拟输入通道
36	11	PB0	I	A	模拟输入通道
37	19	FTP	I/O	A	前置滤波电容连接口
38	20	FTN	I/O	A	前置滤波电容连接口
39	21	AGND	P	P	模拟电源接地端(source: VDDA)
40	22	REFO	P	P	模拟电路基准电压源(source: VDDA)
41	23	OP1N	I	A	OPAMP(OP1) negative input terminal
42	24	OP1O	O	A	OPAMP(OP1) output terminal
43	29	RST	I	S	IC 复位口(Low active)
		VPP	P	P	OTP 读/写时的电压源
44	25	PT1.7/INT1.7/BZ			
		PT1.7	I/O	S/C	通用 I/O 口
		INT1.7	I	S	中断源 INTF1.7
45	-				
		BZ	O	C	蜂鸣器输出端
		PT1.6/INT1.6			
46	-	PT1.6	I/O	S/C	通用 I/O 口
		INT1.6	I	S	中断源 INTF1.6
47	28	PT1.5/INT1.5/TBI1			
		PT1.5	I/O	S/C	通用 I/O 口
		INT1.5	I	S	中断源 INTF1.5
48	29	TBI1	I	S	TimerB 启动输入接口
		PT1.4/INT1.4/TX			
		PT1.4	I/O	S/C	通用 I/O 口
49	30	INT1.4	I	S	中断源 INTF1.4
		TX	O	C	EUART 通讯接口

封装 / 编号 / 脚位		设计			功能说明	
LQFP64	QFN32	名称/功能	型式	缓冲		
48	-	PT1.3/INT1.3/RC				通用 I/O 口 中断源 E3IF EUART 通讯接口
		PT1.3	I/O	S/C		
		INT1.3	I	S		
49	26	PT1.2/INT1.2/LVDIN				通用 I/O 口 中断源 E2IF LVD 外部信号输入接口
		PT1.2	I/O	S/C		
		INT1.2	I	S		
50	-	PT1.1/INT1.1/TBI0				通用 I/O 口 中断源 E1IF TimerB 启动输入接口
		PT1.1	I/O	S/C		
		INT1.1	I	S		
51	27	PT1.0/INT1.0				通用 I/O 口 中断源 E0IF
		PT1.0	I/O	S/C		
51	27	INT1.0	I	S		
		NC	-	-		未使用(不可连接)
62	32	PT2.3/INT2.3/SDA				通用 I/O 口 中断源 INTF2.3 I2C 通讯接口引脚
		PT2.3	I/O	S/C		
		INT2.3	I	S		
63	30	PT2.2/INT2.2/SCL				通用 I/O 口 中断源 INTF2.2 I2C 通讯接口引脚
		PT2.2	I/O	S/C		
		INT2.2	I	S		
64	1	PT2.1/XTI/INT2.1				通用 I/O 口 外接振荡器输入端 中断源 INTF2.1
		PT2.1	I/O	S/C		
		XTI	A	A		
		INT2.1	I	S		

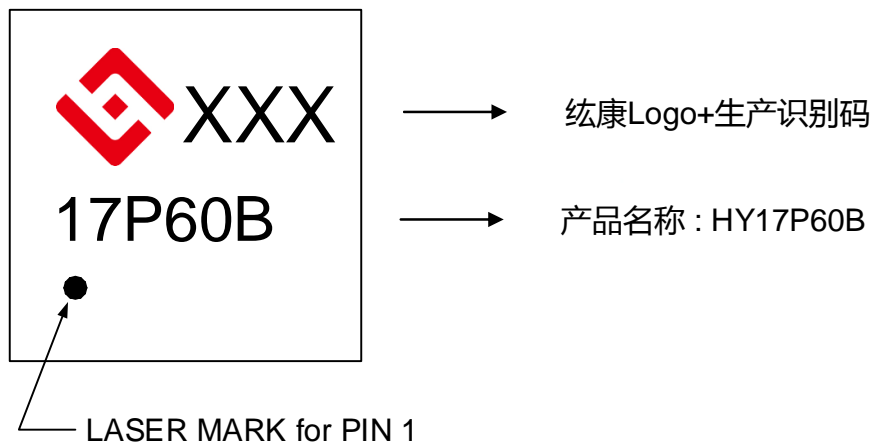
表 2-1 引脚编号与说明

2.2. 封装片标记信息

2.2.1. HY17P60B LQFP 封装片标记信息



2.2.2. HY17P60B QFN 封装片标记信息



3. 应用电路

3.1. HY17P60B 2000 Counts 手动量程 DMM

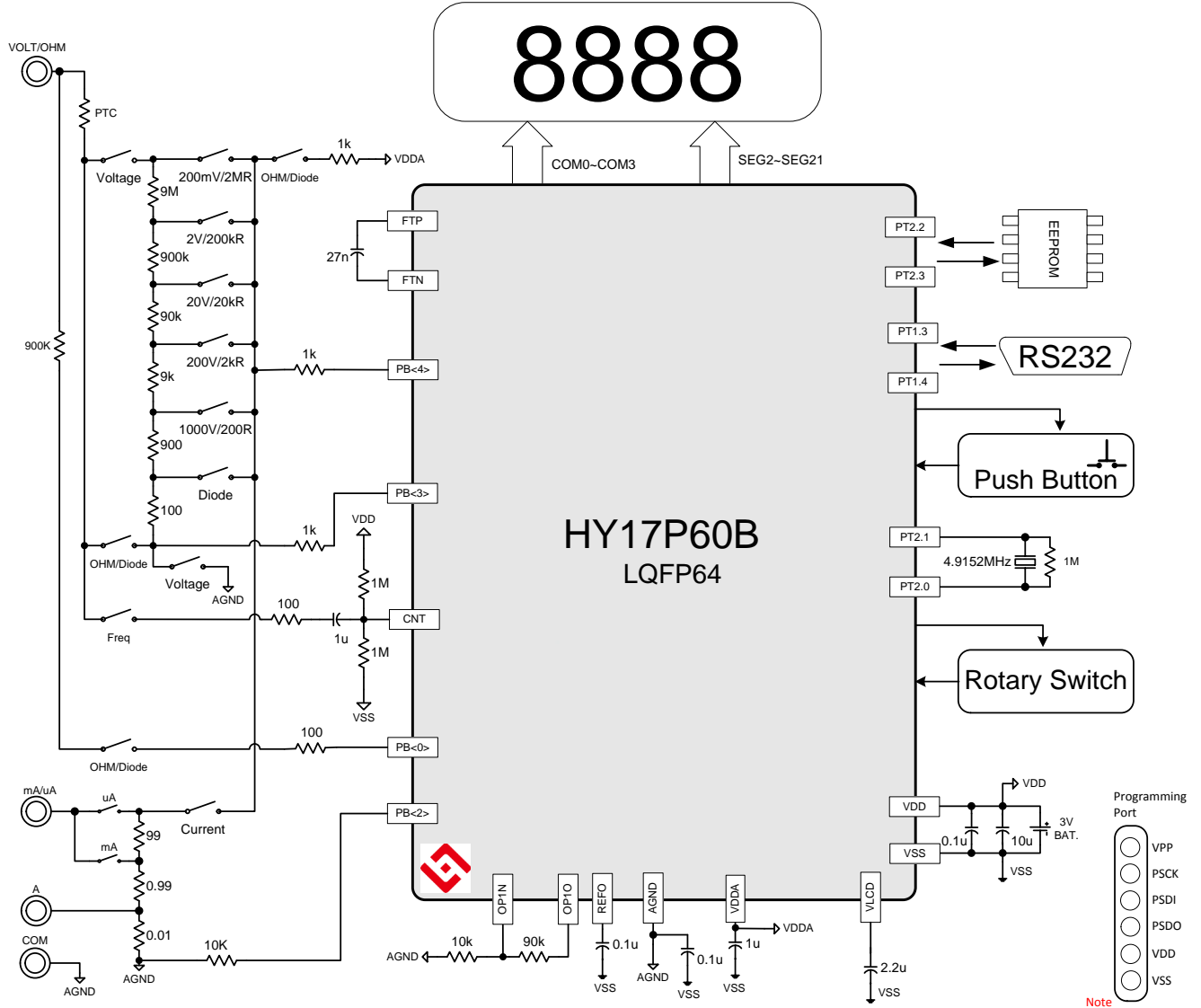


图 3-1 HY17P60B 2000 Counts 手动量程 DMM 应用电路

Note:

HY17P60B 芯片在烧录时不管是否需要同时做 HAO 校正，烧录过程只需要正常接 6 支烧录脚 (VPP、PSCK、PSDI、PSDO、VDD、VSS) 即可进行烧录动作。

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3.2. HY17P60B 红外线传感器

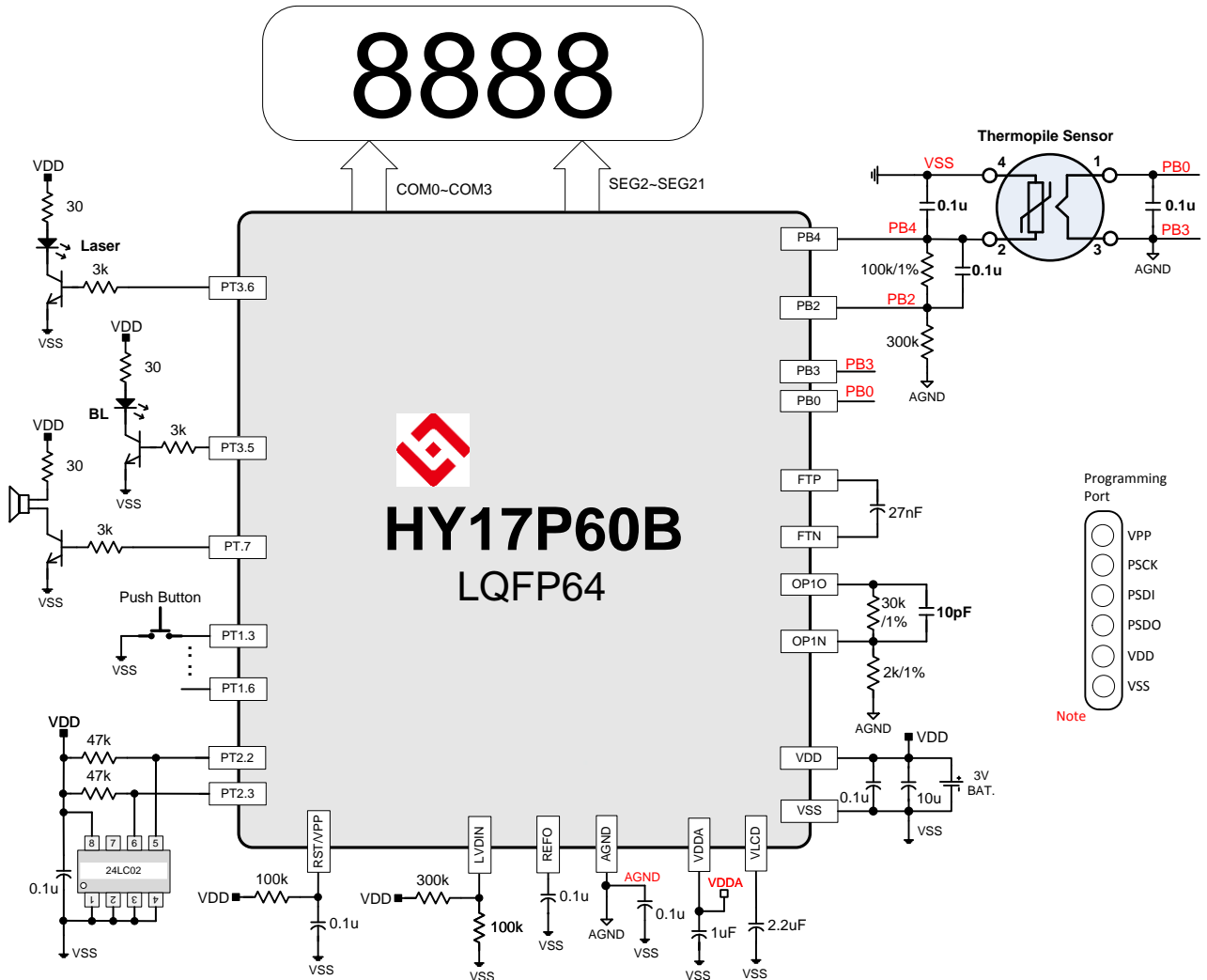


图 3-2 HY17P60B 红外线传感器应用电路

Note:

HY17P60B 芯片在烧录时不管是否需要同时做 HAO 校正，刻录过程只需要正常接 6 支刻烧录 (VPP、PSCK、PSDI、PSDO、VDD、VSS) 即可进行烧录动作。

4. 功能概要

4.1. 内部框图

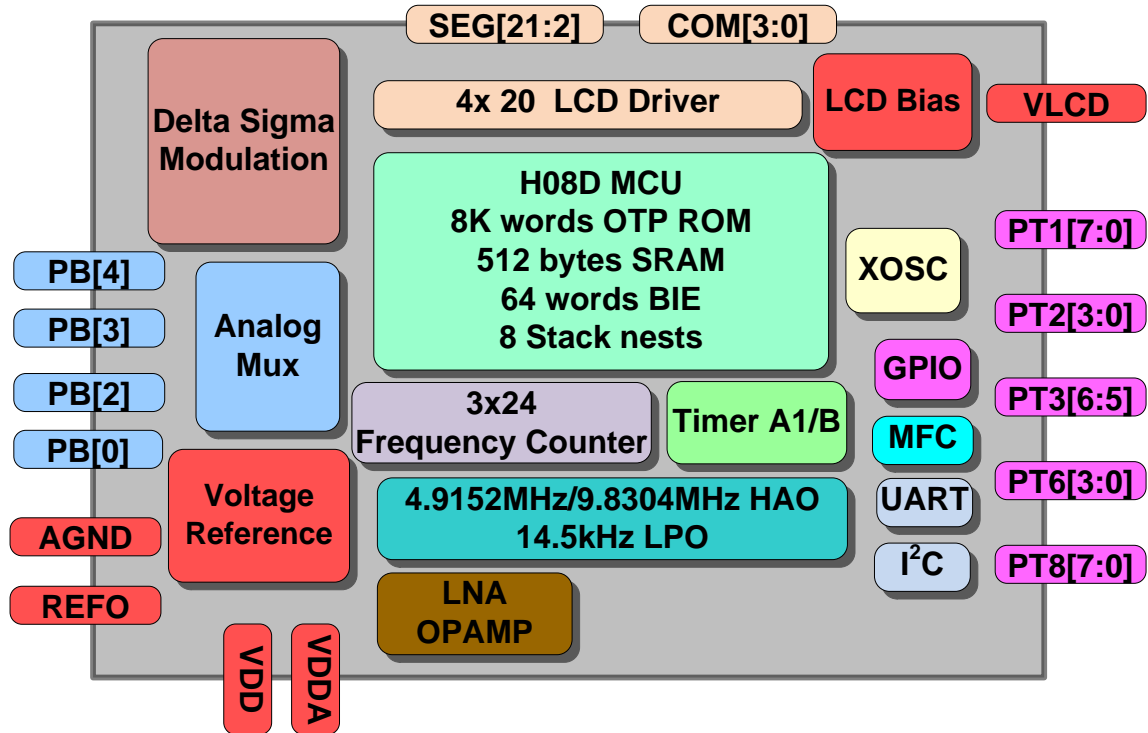


图 4-1 内部方块图

4.2. 相关说明与支持文件

芯片功能相关使用说明书

DS-HY17P60B

UG-HY17S68

APD-CORE002

开发工具相关使用说明书

APD-HY17PIDE001

APD-HY17PIDE005

APD-HYIDE013

APD-HYIDE014

APD-OTP005

产品生产相关使用说明书

APD-HY17PIDE004

HY17P60B 说明书

HY17S68 使用说明书

H08A、H08C、H08D 汇编语言指令集说明书

HY17P 系列开发工具软件使用说明书

HY17P6x 系列开发工具硬件使用说明书

整合型烧录器使用说明书

HY10000-WK08x 整合型烧录器在线更新说明书

OTP 烧录引脚信息

HY17P 系列 HexLoader 说明书

4.3. ADC Network

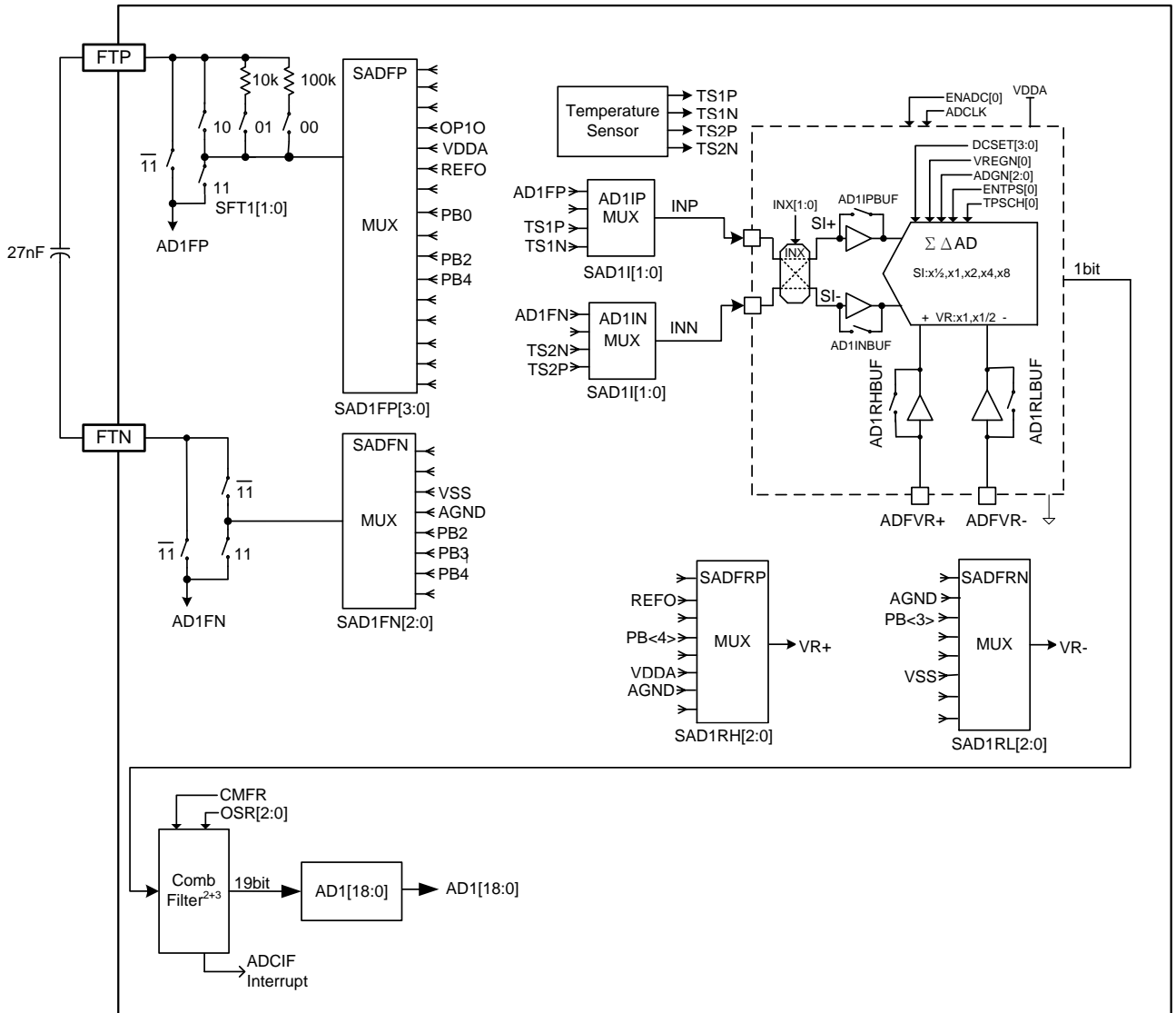


图 4-1 $\Sigma\Delta$ ADC Network 方块图

4.4. Digital Signal Processing(DSP)

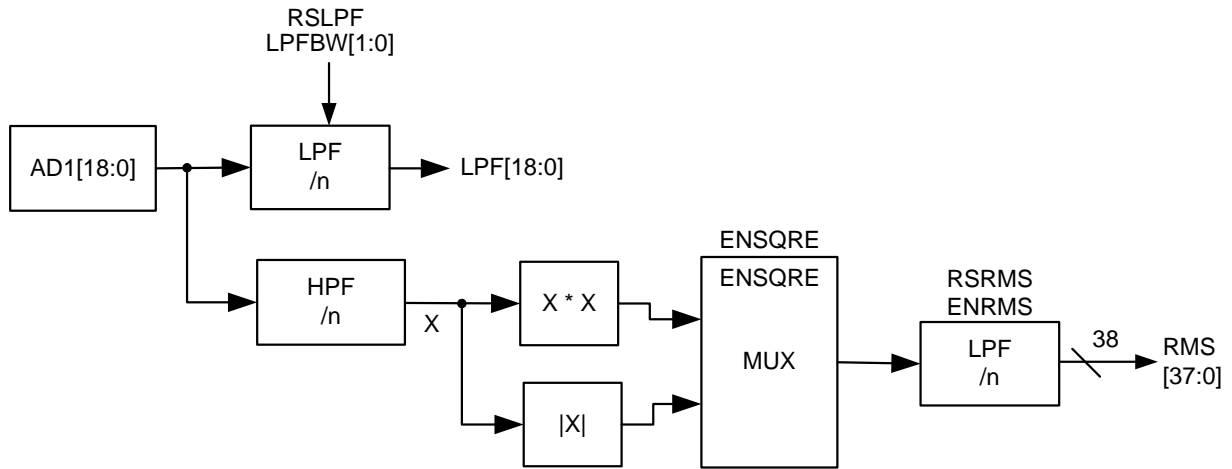


图 4-2 Digital Signal Processing(DSP) 方块图

4.5. Analog Input Network

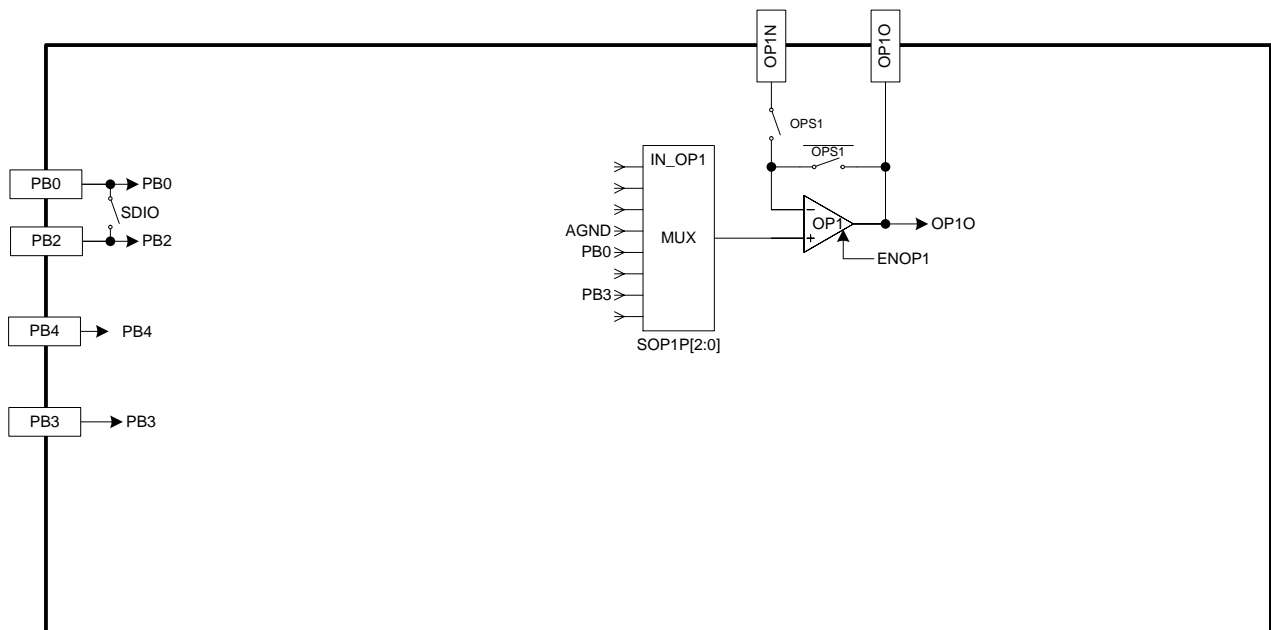


图 4-3 Analog Input Network 方块图

4.6. Clock System

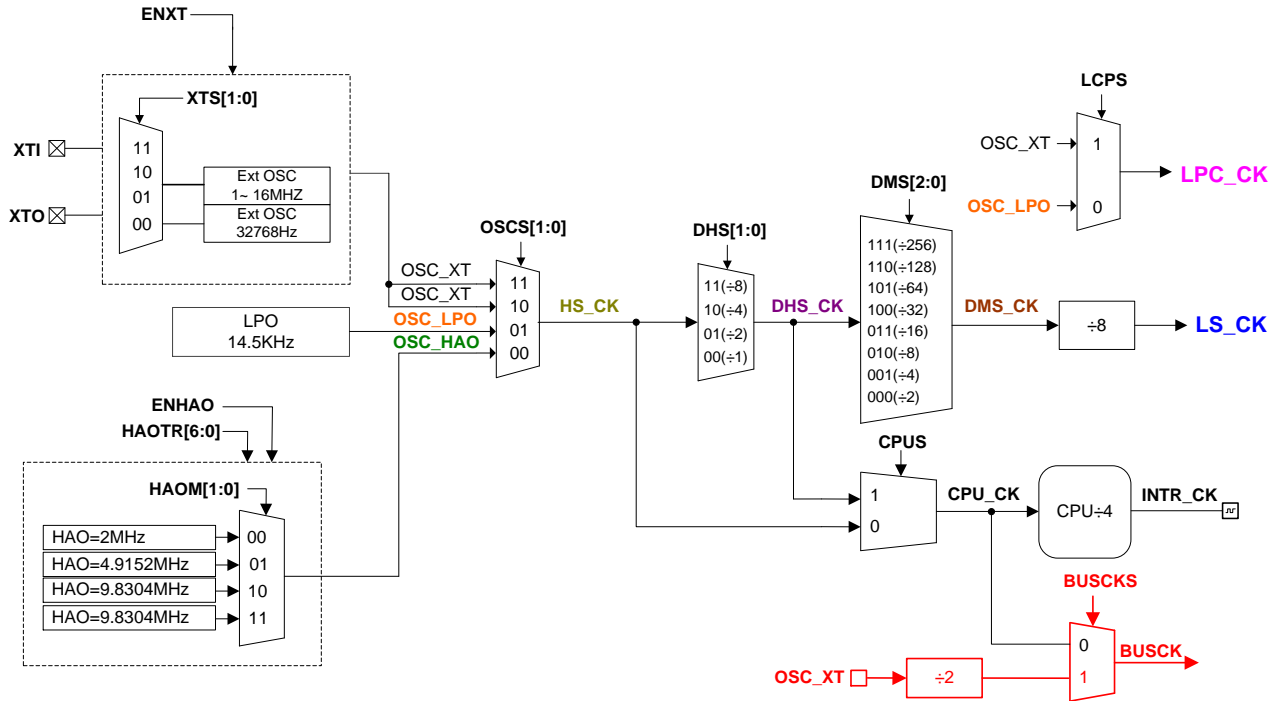


图 4-5-1 HY17P60B Clock System 方块图(一)

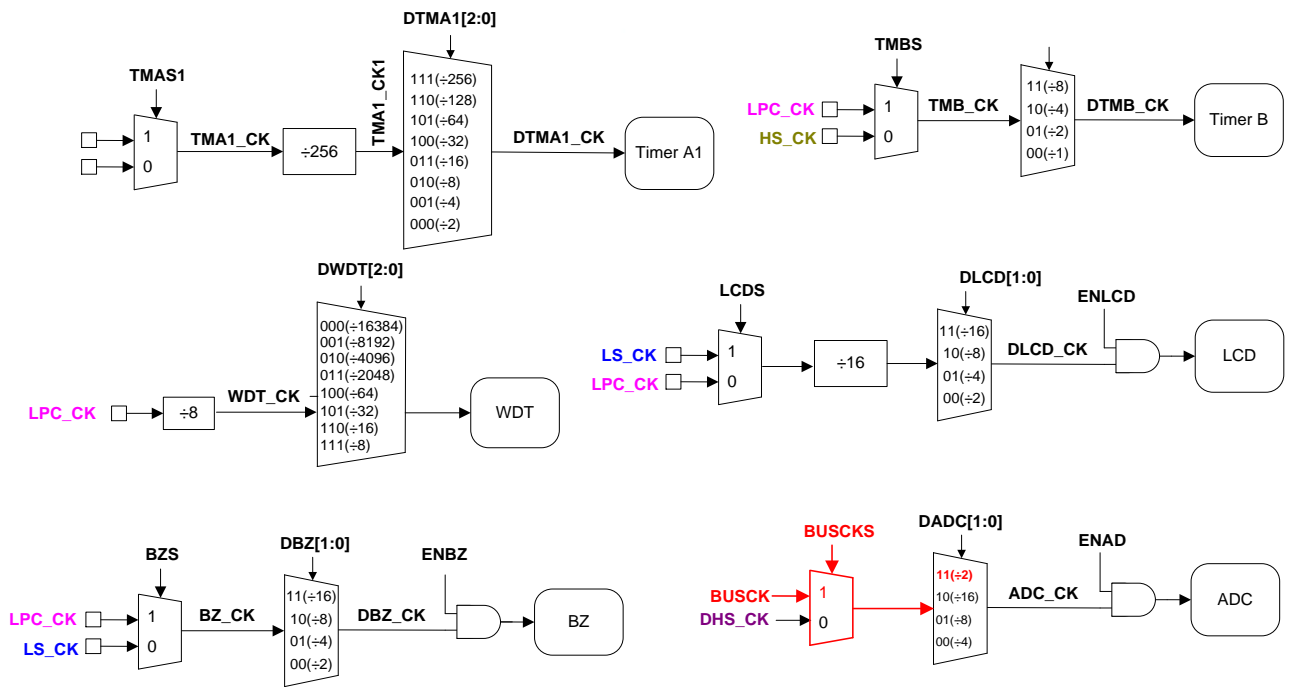


图 4-5-2 HY17P60B Clock System 方块图(二)

4.7. Multi-function Comparator

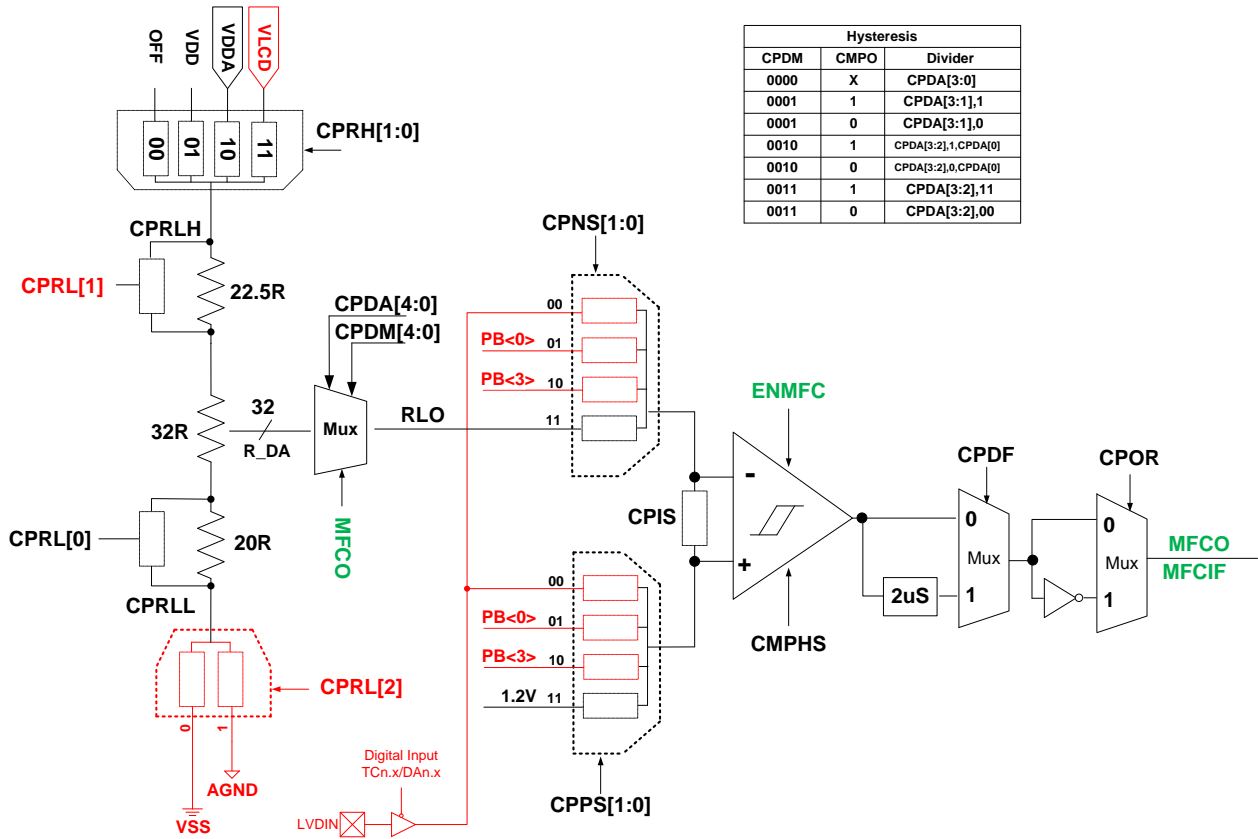


图 4-6 Multi-function Comparator 方块图

4.8. Reset

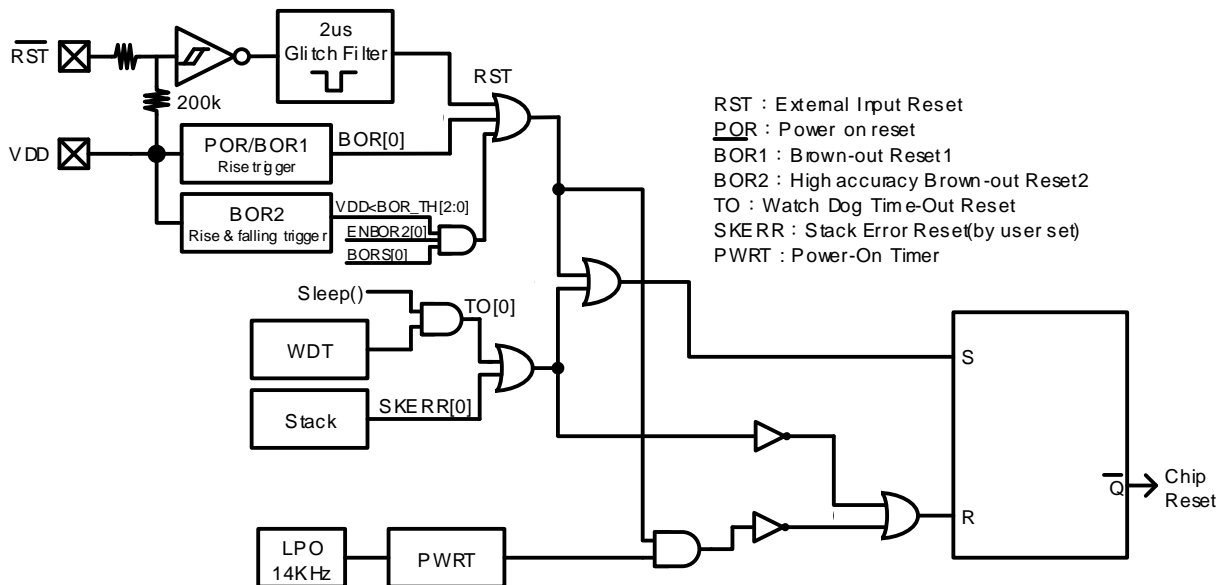


图 4-7 Reset 方块图

4.9. Power Diagram

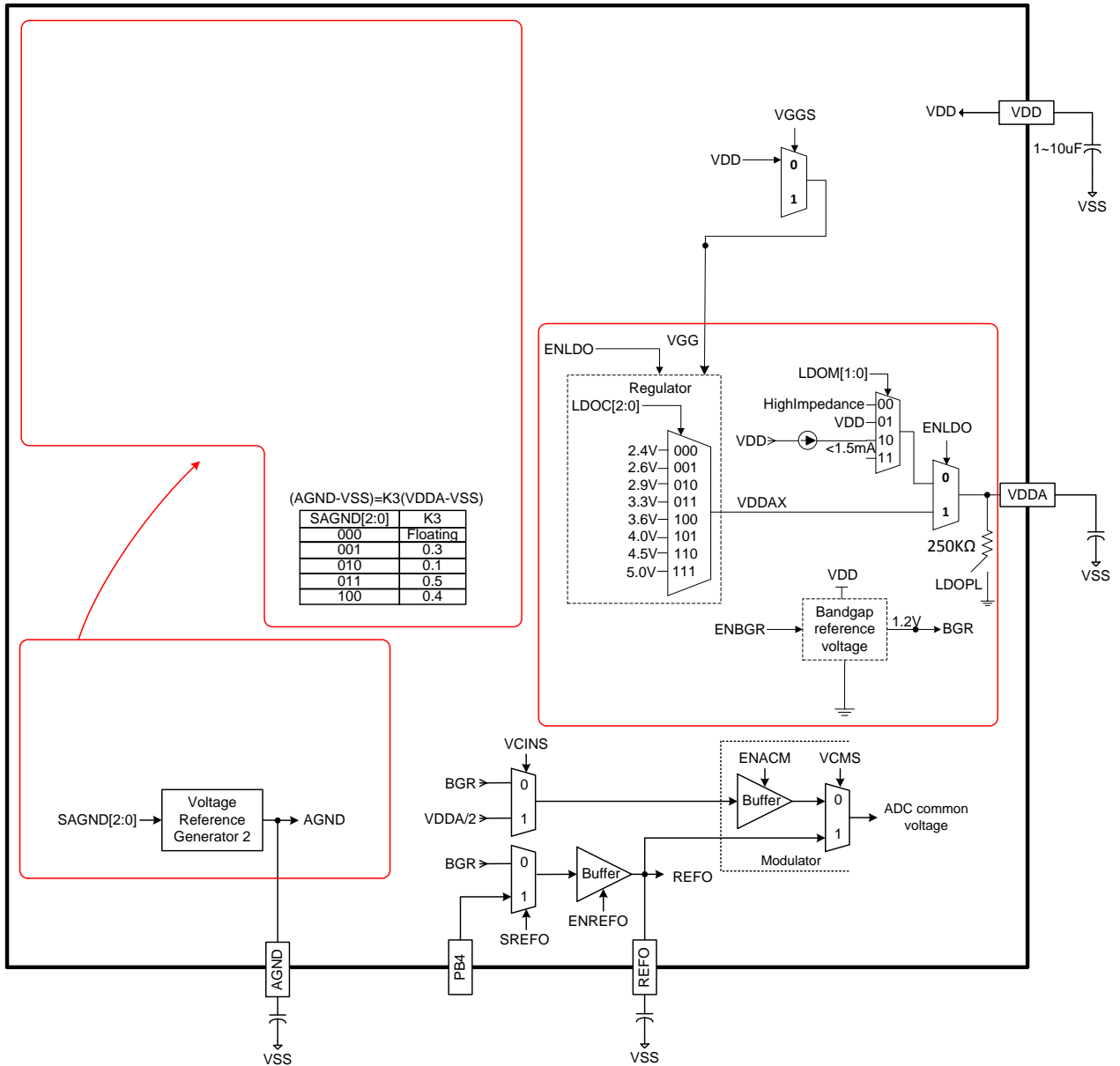


图 4-8 Power System 方块图

4.10. Frequency Counter · CNT Pin

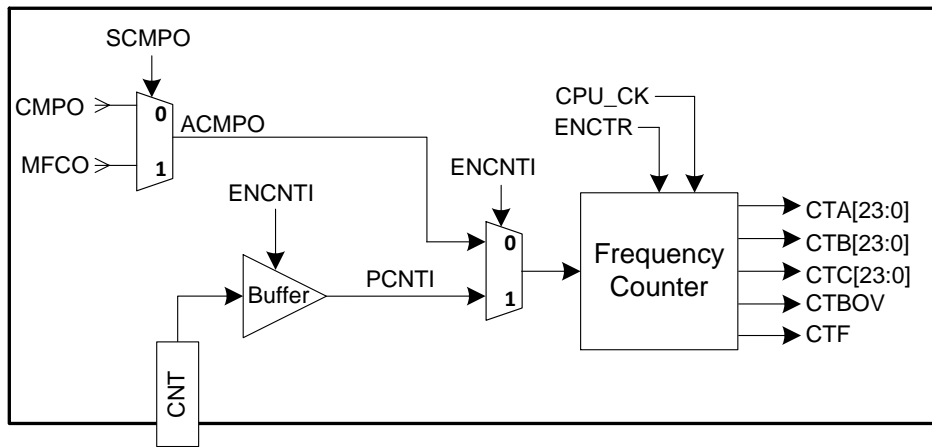


图 4-9 Frequency Counter 方块图

4.11. GPIO PORT1~3

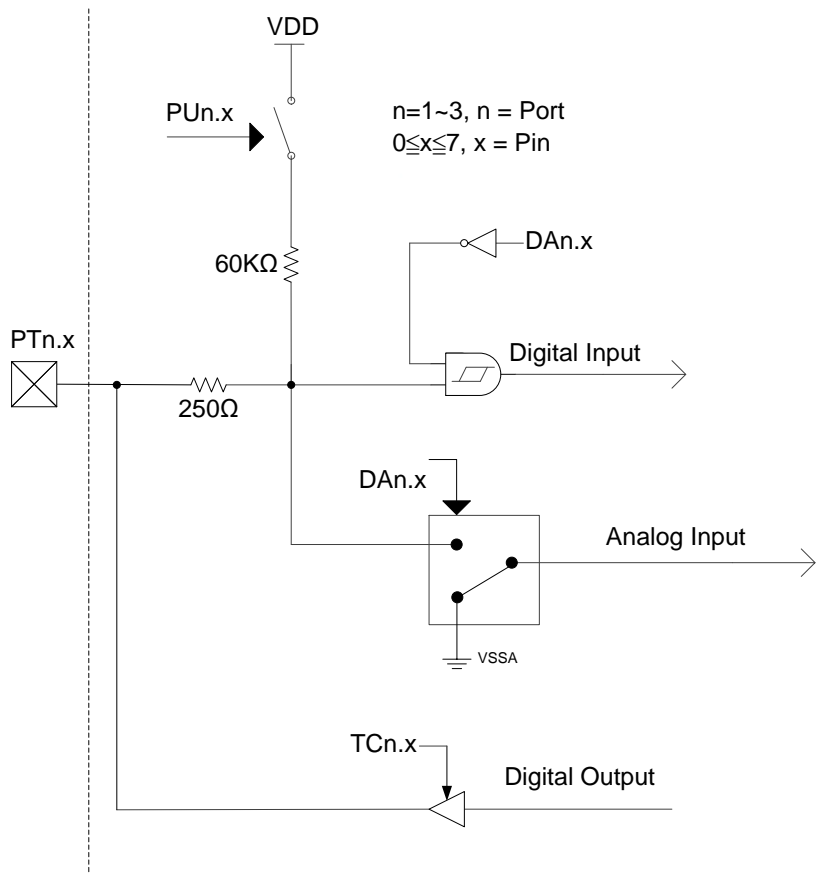


图 4-10 GPIO PORT1~3 方块图

4.12. Watch Dog

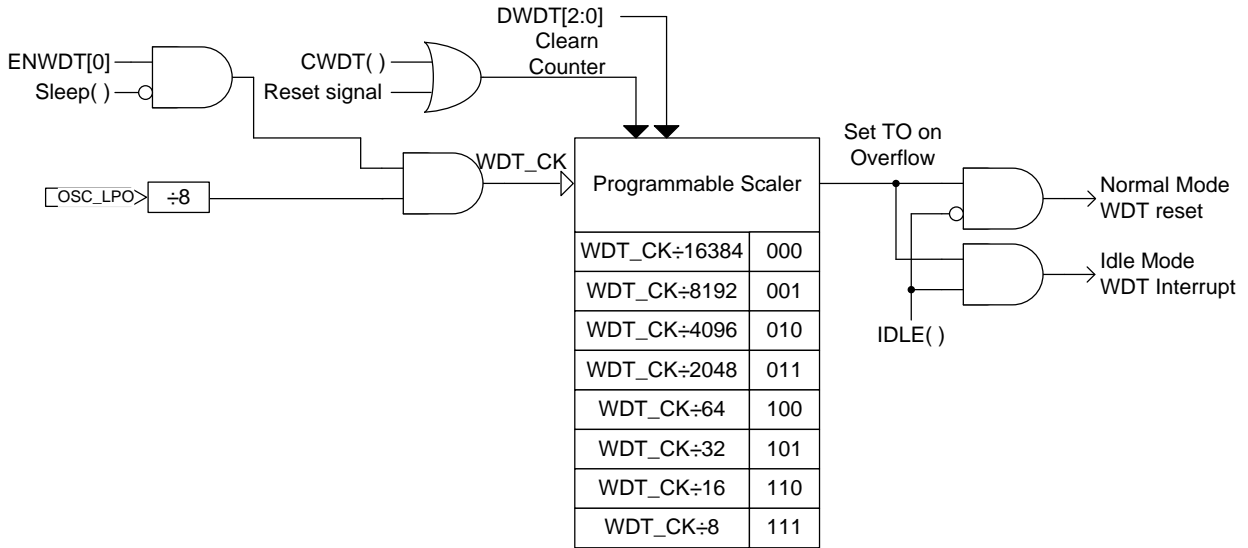


图 4-11 Watch Dog 方块图

4.13. 8-bit Timer A1

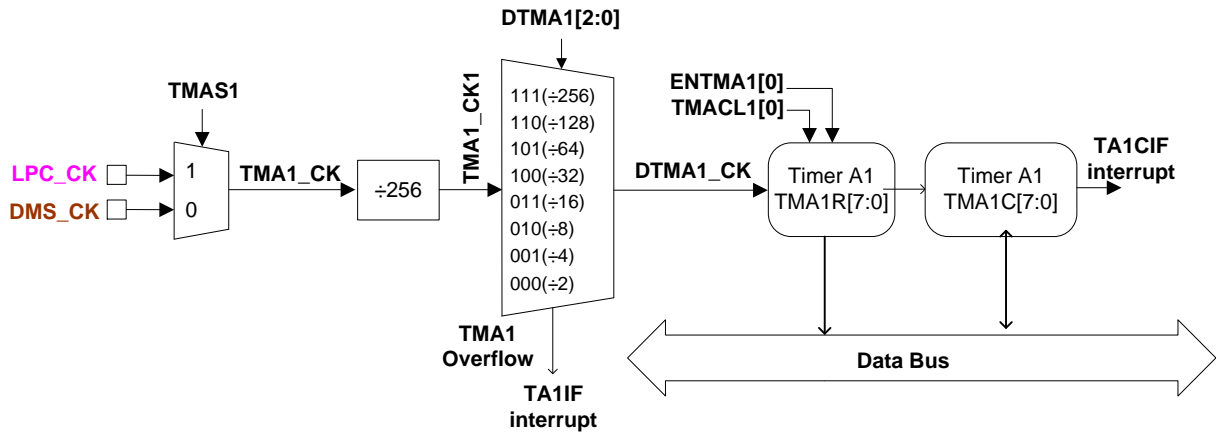


图 4-12 8-bit Timer A1 方块图

4.14. 16-bit Timer B

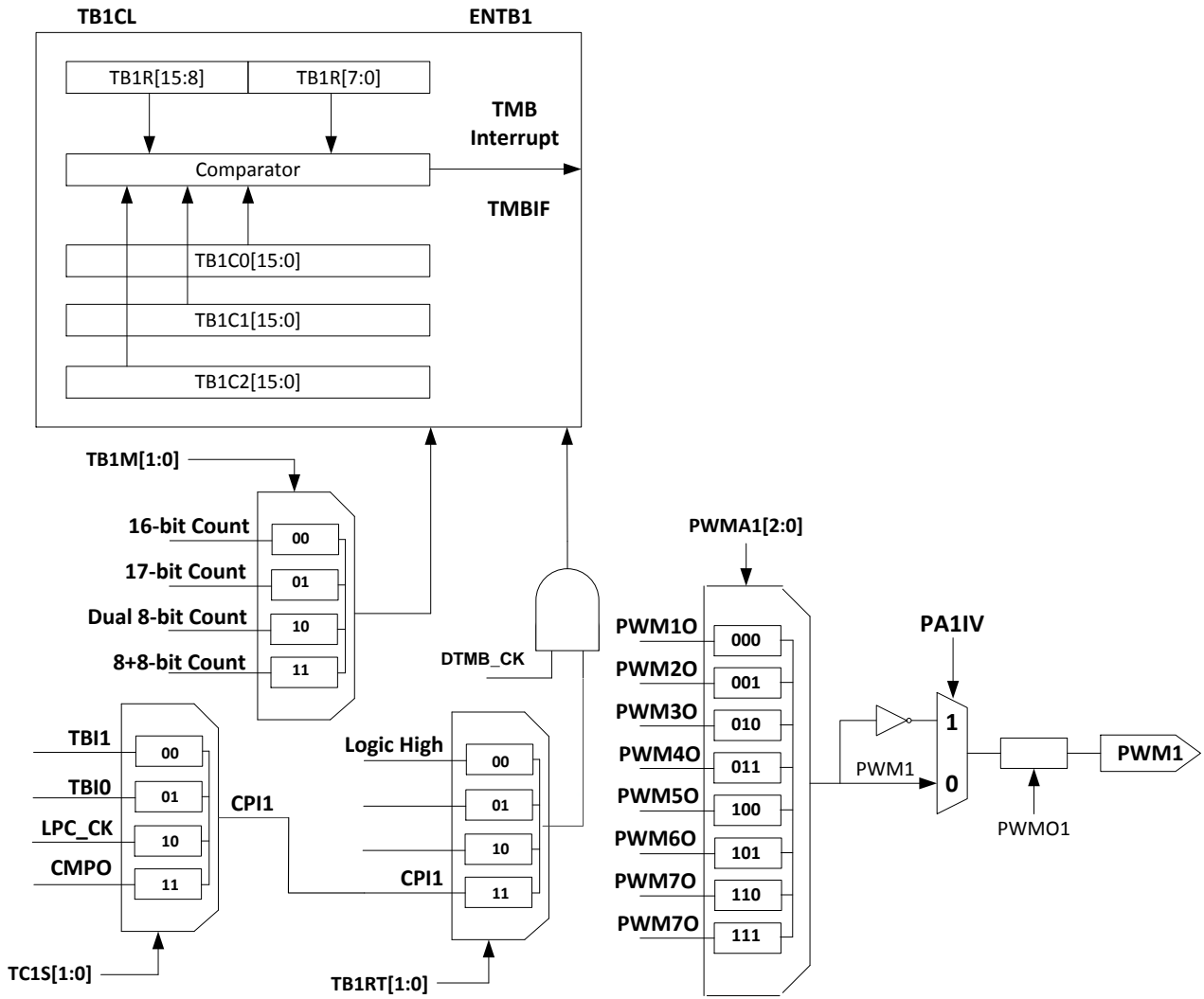


图 4-13 16-bit Timer B 方块图

4.15. LCD

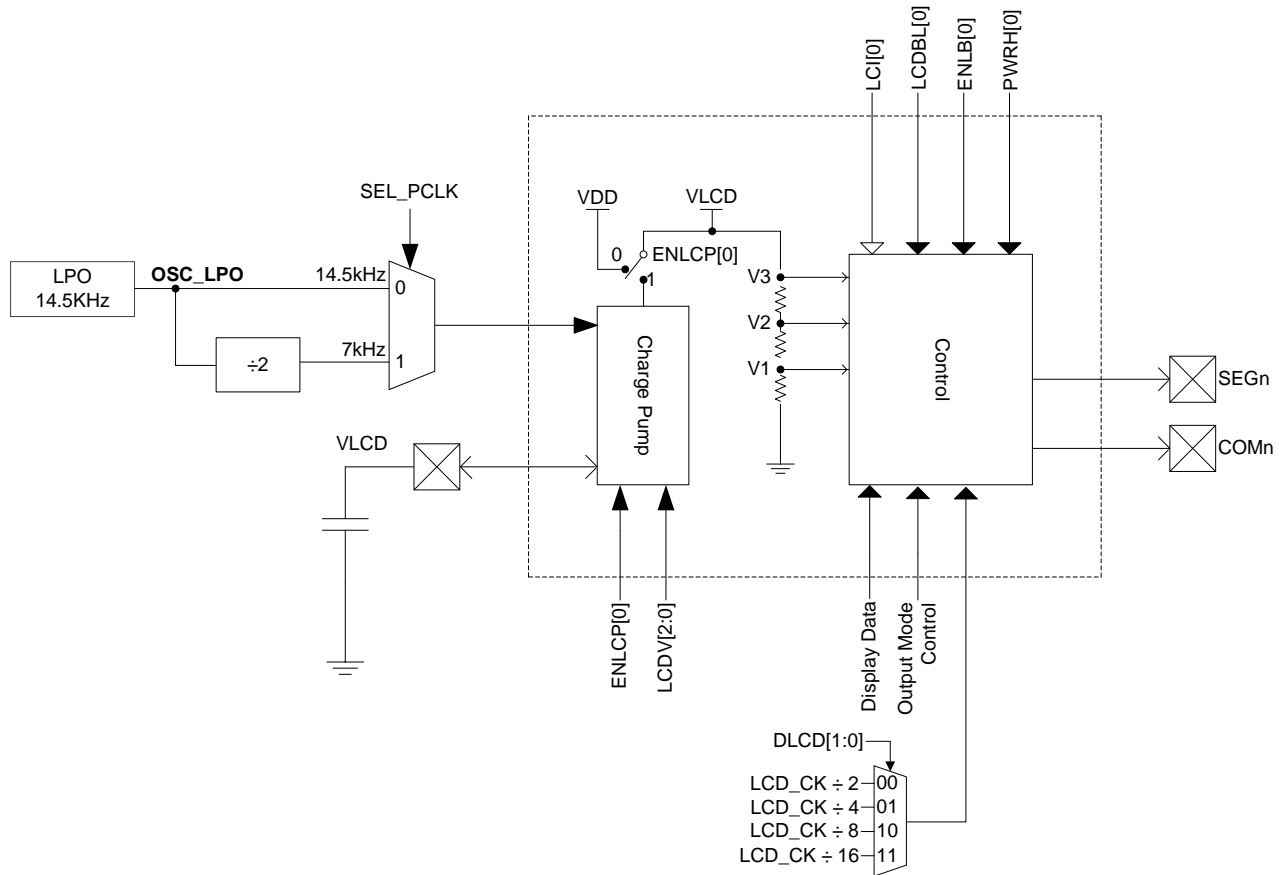


图 4-14 LCD 方块图

4.16. EUART

EUART TRANSMIT BLOCK DIAGRAM

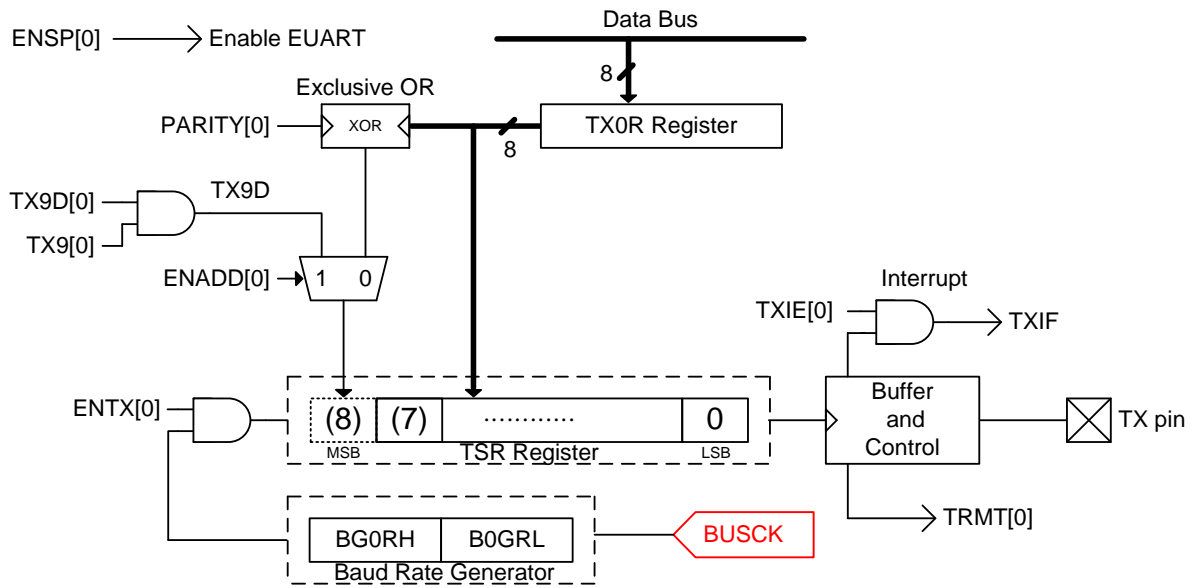
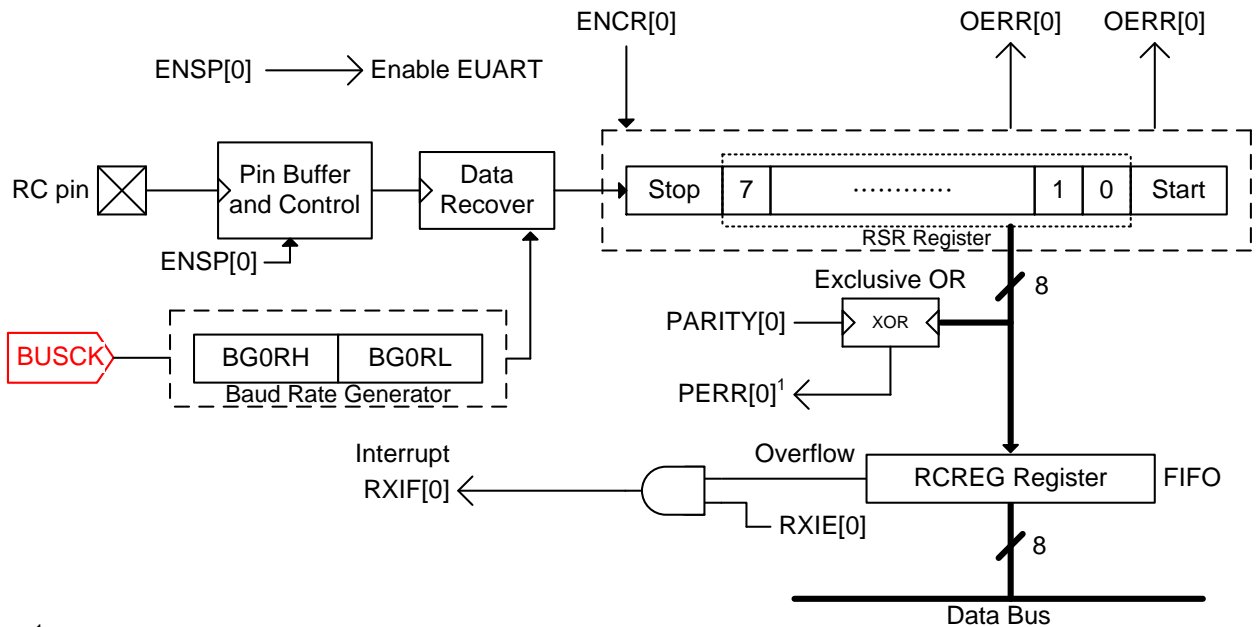


图 4-45-1 HY17P60B EUART 传送方块图

EUART 8-BITS RECEIVE BLOCK DIAGRAM



¹Don't care PERR[0] state of 8-bits receive mode

图 4-55-2 HY17P60B EUART 8-bits 接收方块图

4.17. I²C

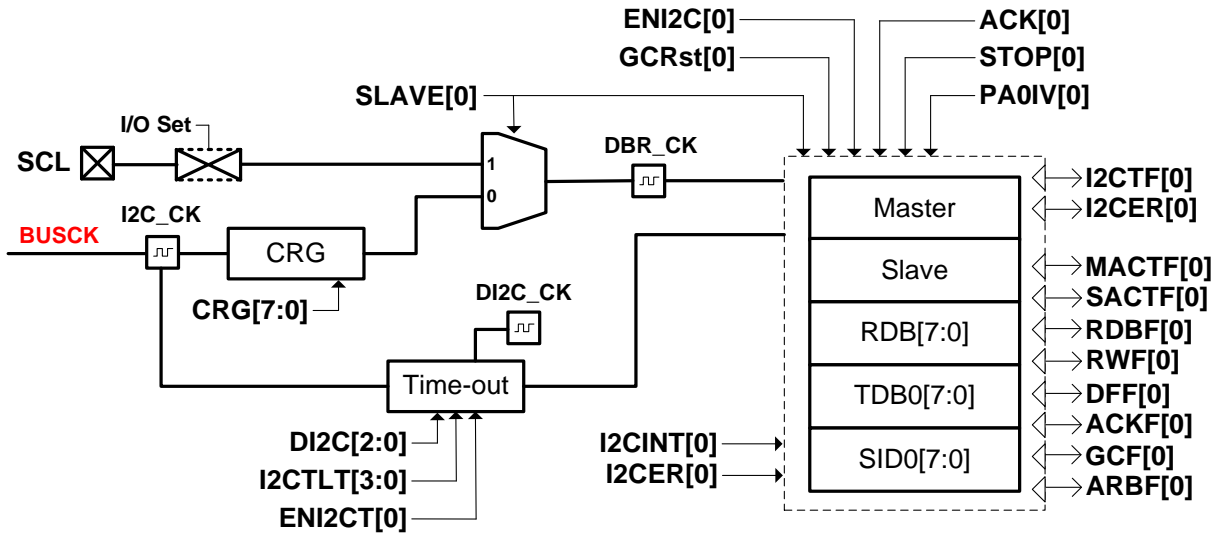


图 4-66 HY17P60B I²C 方块图

5. 寄存器列表

“.”no use,“*”read/write,“w”write,“r”read,“r0”only read 0,“r1”only read 1,“w0”only write 0,“w1”only write 1
“\$”for event status,“.”unimplemented bit,“x”unknown,“u”unchanged,“d”depends on condition

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W
000H	INDF0	Contents of FSR0 to address data memory value of FSR0 not changed								xxxx xxxx	uuuu uuuu	*****
001H	POINC0	Contents of FSR0 to address data memory value of FSR0 post-incremented								xxxx xxxx	uuuu uuuu	*****
002H	PODEC0	Contents of FSR0 to address data memory value of FSR0 post-decremented								xxxx xxxx	uuuu uuuu	*****
003H	PRINC0	Contents of FSR0 to address data memory value of FSR0 pre-incremented								xxxx xxxx	uuuu uuuu	*****
004H	PLUSW0	Contents of FSR0 to address data memory value of FSR0 offset by W								xxxx xxxx	uuuu uuuu	*****
005H	INDF1	Contents of FSR1 to address data memory value of FSR1 not changed								xxxx xxxx	uuuu uuuu	*****
006H	POINC1	Contents of FSR1 to address data memory value of FSR1 post-incremented								xxxx xxxx	uuuu uuuu	*****
007H	PODEC1	Contents of FSR1 to address data memory value of FSR1 post-decremented								xxxx xxxx	uuuu uuuu	*****
008H	PRINC1	Contents of FSR1 to address data memory value of FSR1 pre-incremented								xxxx xxxx	uuuu uuuu	*****
009H	PLUSW1	Contents of FSR1 to address data memory value of FSR1 offset by W								xxxx xxxx	uuuu uuuu	*****
00AH	INDF2	Contents of FSR2 to address data memory value of FSR2 not changed								xxxx xxxx	uuuu uuuu	*****
00BH	POINC2	Contents of FSR2 to address data memory value of FSR2 post-incremented								xxxx xxxx	uuuu uuuu	*****
00CH	PODEC2	Contents of FSR2 to address data memory value of FSR2 post-decremented								xxxx xxxx	uuuu uuuu	*****
00DH	PRINC2	Contents of FSR2 to address data memory value of FSR2 pre-incremented								xxxx xxxx	uuuu uuuu	*****
00EH	PLUSW2	Contents of FSR2 to address data memory value of FSR2 offset by W								xxxx xxxx	uuuu uuuu	*****
00FH	FSR0H	-	-	-	-	-	-	-	FSR0[9:8] xxxx uuuu*
010H	FSR0L	Indirect Data Memory Address Pointer 0 Low Byte,FSR0[7:0]								xxxx xxxx	uuuu uuuu	*****
011H	FSR1H	-	-	-	-	-	-	-	FSR1[9:8]xxx uuuu*
012H	FSR1L	Indirect Data Memory Address Pointer 0 Low Byte,FSR1[7:0]								xxxx xxxx	uuuu uuuu	*****
013H	FSR2H	-	-	-	-	-	-	-	FSR2[9:8]xxx uuuu*
014H	FSR2L	Indirect Data Memory Address Pointer 0 Low Byte,FSR2[7:0]								xxxx xxxx	uuuu uuuu	*****
015H	TOSU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	*****
016H	TOSH	Top-of-Stack High Byte (TOS[12:8])								.xxx xxxx	.uu uuuu*
017H	TOSL	Top-of-Stack Low Byte (TOS[7:0])								xxxx xxxx	uuuu uuuu	*****
018H	SKCN	SKFL	SKUN	SKOV	SKPRT[4:0]				0000 0000	u\$\$\$ \$\$\$	rw 0,rw 0,rw 0,*	
019H	PCLATU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	*****
01AH	PCLATH	PC High Byte for PC[12:8]								.00 0000	.00 0000	*****
01BH	PCLATL	PC Low Byte for PC[7:0]								0000 0000	0000 0000	*****
01CH	TBLPTRU	-	-	-	-	-	-	-	-	xxxx xxxx	uuuu uuuu	*****
01DH	TBLPTRH	Program Memory Table Pointer High Byte (TBLPTR<13:8>)								.xx xxxx	.uu uuuu*
01EH	TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR[7:0])								xxxx xxxx	uuuu uuuu	*****
01FH	TBLDH	Program Memory Table Latch High Byte								xxxx xxxx	uuuu uuuu	*****
020H	TBLDL	Program Memory Table Latch Low Byte								xxxx xxxx	uuuu uuuu	*****
021H	PRODH	Product Register of Multiply High Byte								xxxx xxxx	uuuu uuuu	*****
022H	PRODL	Product Register of Multiply Low Byte								xxxx xxxx	uuuu uuuu	*****
023H	INTE0	GIE	TA1CIE	ADIE	WDTIE	TB1IE	CTIE	E1IE	E0IE	0000 0000	0uuu uuuu	*****
024H	INTE1	TA1IE	-	TXIE	RCIE	I2CERIE	I2CIE	E3IE	E2IE	0000 0000	uuuu uuuu	*****
025H	INTE2	MFCIE	-	-	-	CTBOVE	RMSIE	LPFIE	BOR2IE	.000 0000	.uuu uuuu	*****
026H	INTF0	-	TA1CIF	ADIF	WDTIF	TB1IF	CTF	E1IF	E0IF	.000 0000	.uuu uuuu	*****
027H	INTF1	TA1IF	-	TXIF	RCIF	I2CERIF	I2CIF	E3IF	E2IF	0000 0000	uuuu uuuu	***** r,r,*
028H	INTF2	MFCIF	-	-	-	CTBOV	RMSF	LPFF	BOR2IF	0000 0000	uuuu uuuu	*****
029H	WREG	Working Register								xxxx xxxx	uuuu uuuu	*****
02AH	BSRCN	-	-	-	-	-	-	-	BSR[2:0] xxxx uuuu*
02BH	MSTAT	-	-	-	C	DC	N	OV	Z	.x xxxx	.u uuuu*
02CH	PSTAT	BOR	PD	TO	IDL	RST	SKERR	BOR2LV	GCRstIF	\$000 \$000	uu\$u u\$uu	rw0,rw0,rw0,rw0,rw0,rw0
02DH	BIECN	1	BLKSEL	-	ENBVD	VPPHV	ENBCP	BIEWR	BIERD	1.00 \$000	1.00 \$uuu	r1,.....*
02EH	BIEARH	-	-	BIE High Byte Address Register as BIEA[13:8]						0.xx xxxx	u.uu uuuu*
02FH	BIEARL	BIE Low Byte Address Register as BIEA[7:0]								xxxx xxxx	uuuu uuuu	*****
030H	BIEDRH	BIE High Byte Data Register								xxxx xxxx	uuuu uuuu	*****
031H	BIEDRL	BIE Low Byte Data Register								xxxx xxxx	uuuu uuuu	*****
032H	PWRCN	ENBGR	LDOC[2:0]			LDOM[1:0]		ENLDO	CSFON	1000 0000	1uuu u00u	***** ,w r0,w r0,*
033H	PWRCN1	ENREFO	ENCMP	ENCNT1	ENCTR	ENVS	SAGND[2:0]			0000 0000	uuuu uuuu	*****
034H	PWRCN2	-	VGGS	CHPKS[1:0]		ENFIR	LDLOP	ENTFS	-	0000 0000	uuuu uuuu	*****
035H	OSCCN0	OSCS[1:0]		DHS[1:0]		DMS[2:0]		CUPS	0000 0000	uuuu uuuu	*****	
036H	OSCCN1	COOPT	LCPSS	DADC[1:0]		DTMB[1:0]		TMBS	LCDS	0000 0000	uuuu uu.	*****-
037H	OSCCN2	DLCD[1:0]		ENXT	XTS[1:0]		HAOM[1:0]		ENHAO	0000 0001	uuuu uu1	*****

表 5-1 寄存器列表(续)

HY17P60B

8-Bit RISC-like Mixed Signal Microcontroller Embedded 19-Bit Σ ADC with LNA OPAMP & 4x20 LCD



“-”no use,“*”read/write,“w”write,“r”read,“r0”only read 0,“r1”only read 1,“w0”only write 0,“w1”only write 1
“\$”for event status,“.”unimplemented bit,“x”unknown,“u”unchanged,“d”depends on condition

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W	
038H	CSFCN0	SKRST	HAOTR[6:0]							.1..	*****	
039H	CSFCN1	BUSCK5	-	-	BOR_TH[2:0]			BORS	ENBOR2	0000 0011	uuuu uuuu	*****	
03AH	WDTCN	ENBZ	BZ5	BZ[1:0]		ENWDT	DWDT[2:0]			0000 0000	uuuu \$000	-.*** rw1,***	
03BH	AD1CN0	ENAD1	ENCH	ENINXCH	VREGN	OSR[2:0]		CMFR		000. 0000	uuu. uuuu	*****	
03CH	AD1CN1	ENACM	VCMS	VCINS	TPSCP	TPSCH	ADGN[2:0]			xxxx xxxx	uuuu uuuu	*****	
03DH	AD1CN2	FilterN[1:0]		-	DAFM	DCSET[3:0]			xxxx xxxx	uuuu uuuu	*****		
03EH	AD1CN3	SAD1FP[3:0]			-	SAD1FN[2:0]			xxxx xxxx	uuuu uuuu	*****		
03FH	AD1CN4	AD1RHBUF	AD1RLBUF	AD1PBUF	AD1INBUF	INX[1:0]		VRIS	INIS	0000 0000	uuuu uuuu	*****	
040H	AD1CN5	SAD1RH[2:0]			SAD1RL[2:0]		SAD1I[1:0]			0000 0000	uuuu uuuu	*****	
041H	RMSCN	ENRMS	ENLPF	ENSQRE	LPFBW[1:0]		-	RSLPF	RSRMS	0000 0000	uuuu uuuu	*****	
042H	NET0	SDIO	SREFO	SFT1[1:0]		-	-	-	-	0000 0000	uuuu uuuu	*****	
045H	NET3	-	-	-	SCMPO	-	-	-	CNTI_IF	0000 0000	uuuu uuuu	*****	
04CH	CTAU	CTA[23:16]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
04DH	CTAH	CTA[15:8]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
04EH	CTAL	CTA[7:0]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
04FH	CTBU	CTB[23:16]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
050H	CTBH	CTB[15:8]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
051H	CTBL	CTB[7:0]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
052H	CTCU	CTC[23:16]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
053H	CTCH	CTC[15:8]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
054H	CTCL	CTC[7:0]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
05BH	RMSDATA4	RMS[37:30]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
05CH	RMSDATA3	RMS[29:22]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
05DH	RMSDATA2	RMS[21:14]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
05EH	RMSDATA1	RMS[13:6]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
05FH	RMSDATA0	RMS[5:0]							-	-	xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
060H	LPFDATAU	LPF[18:11]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
061H	LPFDATAH	LPF[10:3]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
062H	LPFDATAL	LPF[2:0]							-	-	xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
063H	AD1DATAU	AD1[18:11]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
064H	AD1DATAH	AD1[10:3]							xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r		
065H	AD1DATAL	AD1[2:0]							-	-	xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
066H	OP1CN0	ENOP1	SOP1P[2:0]			-	-	-	OPS1	0000 0000	uuuu uuuu	*****	
068H	TMA1CN	ENTMA1	TMACL1	TMAS1	DTMA1[2:0]			-	-	0000 00.0	u0uu uu.u	*,rw1,*,*,*,*	
069H	TMA1R	TMA1 counter Register							0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0 rw0,rw0,rw0,rw0		
06AH	TMA1C	TMA1C counter Register							0000 0000	uuuu uuuu	rw0,rw0,rw0,rw0 rw0,rw0,rw0,rw0		
06BH	PT1	PT1.7	PT1.6	PT1.5	PT1.4	PT1.3	PT1.2	PT1.1	PT1.0	xxxx xxxx	uuuu uuuu	*****	
06CH	PT1IN	IN1.7	IN1.6	IN1.5	IN1.4	IN1.3	IN1.2	IN1.1	IN1.0	0000 0000	uuuu uuuu	*****	
06DH	TRISC1	TC1.7	TC1.6	TC1.5	TC1.4	TC1.3	TC1.2	TC1.1	TC1.0	0000 0000	uuuu uuuu	*****	
06EH	PT1PU	PU1.7	PU1.6	PU1.5	PU1.4	PU1.3	PU1.2	PU1.1	PU1.0	0000 0000	uuuu uuuu	*****	
06FH	PT1M1	-	-	-	-	INTEG1[1:0]		INTEG0[1:0]		0000 0000	uuuu uuuu	*****	
070H	PT1INT	INTEG7	INTEG6	INTEG5	INTEG4	INTEG3	INTEG2	-	-	0000 0000	uuuu uuuu	*****	
071H	PT1INTE	INTE1.7	INTE1.6	INTE1.5	INTE1.4	-	-	-	-	0000 0000	uuuu uuuu	*****	
072H	PT1INTF	INTF1.7	INTF1.6	INTF1.5	INTF1.4	-	-	-	-	0000 0000	uuuu uuuu	*****	
073H	PT2	-	-	-	-	PT2.3	PT2.2	PT2.1	PT2.0	xxxx xxxx	uuuu uuuu	*****	
074H	PT2IN	-	-	-	-	IN2.3	IN2.2	IN2.1	IN2.0	0000 0000	uuuu uuuu	*****	
075H	TRISC2	-	-	-	-	TC2.3	TC2.2	TC2.1	TC2.0	0000 0000	uuuu uuuu	*****	
076H	PT2PU	-	-	-	-	PU2.3	PU2.2	PU2.1	PU2.0	0000 0000	uuuu uuuu	*****	
077H	PT2INT	-	-	-	-	INTG2.3	INTG2.2	INTG2.1	INTG2.0	0000 0000	uuuu uuuu	*****	
078H	PT2INTE	-	-	-	-	INTE2.3	INTE2.2	INTE2.1	INTE2.0	0000 0000	uuuu uuuu	*****	
079H	PT2INTF	-	-	-	-	INTF2.3	INTF2.2	INTF2.1	INTF2.0	0000 0000	uuuu uuuu	*****	
07AH	MFCN0	CPRH[1:0]		MFCO	CPIS	CPOR	CPDF	CMPHS	ENMFC	0000 0000	uuuu uuuu	*****	
07BH	MFCN1	CPRL[2:0]			-	CPPS[1:0]		CPNS[1:0]		0000 0000	uuuu uuuu	*****	
07CH	MFCN2	-	-	-	CPDA[4:0]				0000 0000	uuuu uuuu	*****		
07DH	MFCN3	-	-	-	CPDM[4:0]				0000 0000	uuuu uuuu	*****		

表 5-2 寄存器列表(续)

HY17P60B

8-Bit RISC-like Mixed Signal Microcontroller Embedded 19-Bit Σ ADC with LNA OPAMP & 4x20 LCD



“\$”for event status,“.”unimplemented bit,“x”unknown,“u”unchanged,“d”depends on condition

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	ARST	IRST	R/W		
180H	LCDCN1	ENLCP	LCDV[2:0]			ENLB	SELPCLK	LCDBL	ENLCD	0000 0000	uuuu uuuu	*****		
182H	LCDCN3	SCM3[1:0]		SCM2[1:0]		SCM1[1:0]		SCM0[1:0]		0000 0000	uuuu uuuu	*****		
183H	LCDCN4	SSG21	SSG20	SSG19	SSG18	SSG17	SSG16	SSG15	SSG14	0000 0000	uuuu uuuu	*****		
185H	LCDCN6	SSG5[1:0]		SSG4[1:0]		SSG3[1:0]		SSG2[1:0]		0000 0000	uuuu uuuu	*****		
186H	LCDCN7	SSG9[1:0]		SSG8[1:0]		SSG7[1:0]		SSG6[1:0]		0000 0000	uuuu uuuu	*****		
187H	LCDCN8	SSG13[1:0]		SSG12[1:0]		SSG11[1:0]		SSG10[1:0]		0000 0000	uuuu uuuu	*****		
18BH	LCD0	LCD SEG3[4:7] data				LCD SEG2[3:0] data				xxxx xxxx	uuuu uuuu	*****		
18CH	LCD1	LCD SEG5[4:7] data				LCD SEG4[3:0] data				xxxx xxxx	uuuu uuuu	*****		
18DH	LCD2	LCD SEG7[4:7] data				LCD SEG6[3:0] data				xxxx xxxx	uuuu uuuu	*****		
18EH	LCD3	LCD SEG9[4:7] data				LCD SEG8[3:0] data				xxxx xxxx	uuuu uuuu	*****		
18FH	LCD4	LCD SEG11[4:7] data				LCD SEG10[3:0] data				xxxx xxxx	uuuu uuuu	*****		
190H	LCD5	LCD SEG13[4:7] data				LCD SEG12[3:0] data				xxxx xxxx	uuuu uuuu	*****		
191H	LCD6	LCD SEG15[4:7] data				LCD SEG14[3:0] data				xxxx xxxx	uuuu uuuu	*****		
192H	LCD7	LCD SEG17[4:7] data				LCD SEG16[3:0] data				xxxx xxxx	uuuu uuuu	*****		
193H	LCD8	LCD SEG19[4:7] data				LCD SEG18[3:0] data				xxxx xxxx	uuuu uuuu	*****		
194H	LCD9	LCD SEG21[4:7] data				LCD SEG20[3:0] data				xxxx xxxx	uuuu uuuu	*****		
19FH	PT3	-	PT3.6	PT3.5	-	-	-	-	-	xxxx xxxx	uuuu uuuu	*****		
1A0H	PT3IN	-	IN3.6	IN3.5	-	-	-	-	-	0000 0000	uuuu uuuu	*****		
1A1H	TRISC3	-	TC3.6	TC3.5	-	-	-	-	-	0000 0000	uuuu uuuu	*****		
1A2H	PT3PU	-	PU3.6	PU3.5	-	-	-	-	-	0000 0000	uuuu uuuu	*****		
1A8H	PT6	-	-	-	-	PT6.3	PT6.2	PT6.1	PT6.0	xxxx xxxx	uuuu uuuu	*****		
1A9H	PT6IN	-	-	-	-	IN6.3	IN6.2	IN6.1	IN6.0	0000 xxxx	uuuu uuuu	*****		
1AAH	TRISC6	-	-	-	-	TC6.3	TC6.2	TC6.1	TC6.0	0000 xxxx	uuuu uuuu	*****		
1ABH	PT6PU	-	-	-	-	PU6.3	PU6.2	PU6.1	PU6.0	0000 xxxx	uuuu uuuu	*****		
1B0H	PT8	PT8.7	PT8.6	PT8.5	PT8.4	PT8.3	PT8.2	PT8.1	PT8.0	xxxx xxxx	uuuu uuuu	*****		
1B1H	PT8IN	IN8.7	IN8.6	IN8.5	IN8.4	IN8.3	IN8.2	IN8.1	IN8.0	0000 0000	uuuu uuuu	*****		
1B2H	TRISC8	TC8.7	TC8.6	TC8.5	TC8.4	TC8.3	TC8.2	TC8.1	TC8.0	0000 0000	uuuu uuuu	*****		
1B3H	PT8PU	PU8.7	PU8.6	PU8.5	PU8.4	PU8.3	PU8.2	PU8.1	PU8.0	0000 0000	uuuu uuuu	*****		
1C3H	CFG0	-	-	-	-	-	GCRst	ENI2CT	ENI2C	0000 0000 uuuu	~.....*		
1C4H	ACT0	SLAVE	-	-	I2CER	START	STOP	I2CINT	ACK	0000 0000	uuuu uuuu	*****		
1C5H	STA0	MACTF	SACTF	RDBF	RWF	DFF	ACKF	GCF	ARBF	0001 0000	uuuu uuuu	*****		
1C6H	CRG0	CRG[7:0]								0000 0000	uuuu uuuu	*****		
1C7H	TOC0	I2CTF	DI2C[2:0]			I2CTL[3:0]				0000 0000	uuuu uuuu	*****		
1C8H	RDB0	RDB[7:1]							RDB[0]	xxxx xxxx	uuuu uuuu	*****		
1C9H	TDB0	TDB[7:1]							TDB[0]	xxxx xxxx	uuuu uuuu	*****		
1CAH	SID0	SID0[7:1],The corresponding address of the 7-bit mode							SID0[0]	0000 0000	uuuu uuuu	*****		
1CBH	UR0CN	ENSP	ENTX	TX9	TX9D	PARITY	-	-	WUE	0000 0..0	uuuu u..u	*****		
1CCH	UR0STA	-	RC9D	PERR	FERR	OERR	RCIDL	TRMT	ABDOVF	.000 0010	..uu uuuu	~.r,r,r r,r,r,rw0		
1CDH	BA0CN	-	-	-	-	ENCR	RC9	ENADD	ENABD 0000 uuuu	~.....*		
1CEH	BG0RH	-	-	-	Baud Rate Generator Register High Byte				...x xxxx	...u uuuu	~.....*			
1CFH	BG0RL	Baud Rate Generator Register Low Byte							xxxx xxxx	uuuu uuuu	*****			
1D0H	TX0R	UART Transmit Register										xxxx xxxx	uuuu uuuu	*****
1D1H	RC0REG	UART Receive Register										xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
1D2H	TB1Flag		PWM7A	PWM6A	PWM5A	PWM4A	PWM3A	PWM2A	PWM1A	.000 0000	..uuu uuuu	~.r,r,r r,r,r,r		
1D3H	TB1CN0	ENTB1	TB1M[1:0]		TB1RT[1:0]		TB1CL	PWMO1	PWMO0	0000 0000	uuuu u0uu	*****~rw1,~*		
1D4H	TB1CN1	PA1IV	PWMA1[2:0]			PA0IV	PWMA0[2:0]			0000 0000	uuuu uuuu	*****		
1D5H	TB1RH	TimerB1 counter Register [15:8]										xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
1D6H	TB1RL	TimerB1 counter Register [7:0]										xxxx xxxx	uuuu uuuu	r,r,r,r r,r,r,r
1D7H	TB1C0H	TimerB1 counter Condition Register [15:8]										xxxx xxxx	uuuu uuuu	*****
1D8H	TB1C0L	TimerB1 counter Condition Register [7:0]										xxxx xxxx	uuuu uuuu	*****
1D9H	TB1C1H	TimerB1 counter Condition Register [15:8]										xxxx xxxx	uuuu uuuu	*****
1DAH	TB1C1L	TimerB1 counter Condition Register [7:0]										xxxx xxxx	uuuu uuuu	*****
1DBH	TB1C2H	TimerB1 counter Condition Register [15:8]										xxxx xxxx	uuuu uuuu	*****
1DCH	TB1C2L	TimerB1 counter Condition Register [7:0]										xxxx xxxx	uuuu uuuu	*****
1E2H	FILTER	FreSpect		Frebit	ENSpect	-	-	-	-	0000 0000	uuuu uuuu	*****		
080h ~ 0FFh	SRAM as 128Byte										uuuu uuuu	uuuu uuuu	*****	
100h ~ 17Fh	SRAM as 128Byte										uuuu uuuu	uuuu uuuu	*****	
200h ~ 2FFh	SRAM as 256Byte										uuuu uuuu	uuuu uuuu	*****	

表 5-3 寄存器列表(续)

6. 电气特性

Absolute Maximum Ratings:

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at V _{DD} to V _{SS}	-0.2 V to 6.0 V
Voltage applied to any pin	-0.2 V to V _{DD} + 0.3 V
Voltage applied to RST/VPP pin	-0.2 V to 8.75 V
Diode current at any device terminal	±2 mA
Storage temperature, Tstg: (unprogrammed device)	-55°C to 125°C
(programmed device)	-40°C to 85°C
Total power dissipation.	0.5W
Maximum output current sink by any I/O pin.20mA

6.1. Recommended operating conditions

T_A = -40°C ~ 85°C, unless otherwise noted

Sym.	Parameter		Test Conditions	Min.	Typ.	Max.	Unit
V _{DD}	Supply Voltage		All digital peripherals and CPU V _{DD} = 2.2V~5.5V, Frequency<=9.6MHz, V _{DD} = 3.6V~5.5V, Frequency<=16MHz,	2.2		5.5	V
V _{DDA}	Supply Voltage		Analog peripherals	2.4		4.5	
V _{SS}	Supply Voltage			0		0	
XT	External Oscillator Frequency	Watch crystal	V _{DD} = 2.5V~5.5V, ENXT[0]=1	XTS[1:0]=0x	32768		Hz
		Ceramic resonator, Crystal		XTS[1:0]=10	450K	4M	
				XTS[1:0]=11	1M	8M	
		Ceramic resonator, Crystal	V _{DD} = 3.6V~5.5V, ENXT[0]=1	XTS[1:0]=11	450K	16M	

6.2. Internal RC Oscillator

T_A = 25°C, V_{DD} = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
HAO	High Speed Oscillator frequency	ENHAO[0]=1, HAOM[1:0]=01	-20%	4.9152	+20%	MHz
		ENHAO[0]=1, HAOM[1:0]=11	-20%	9.8304	+20%	
LPO	Low Power Oscillator frequency	V _{DD} supply voltage be enable LPO	-20%	14.5	+20%	kHz

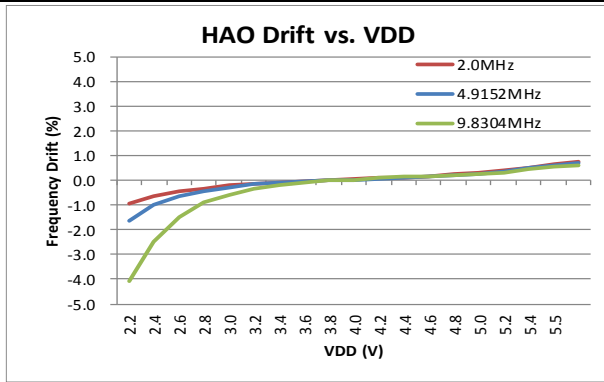


Figure 6.2-1 HAO vs. VDD

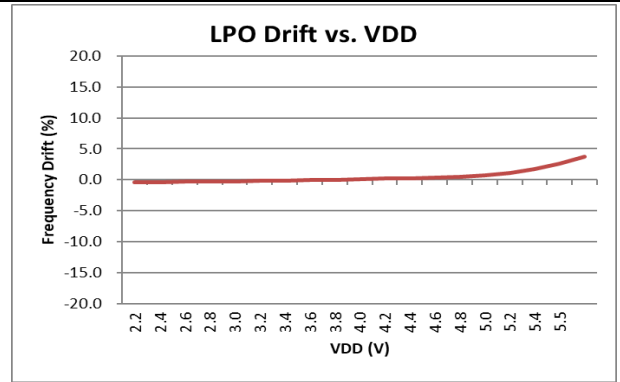


Figure 6.2-2 LPO vs. VDD

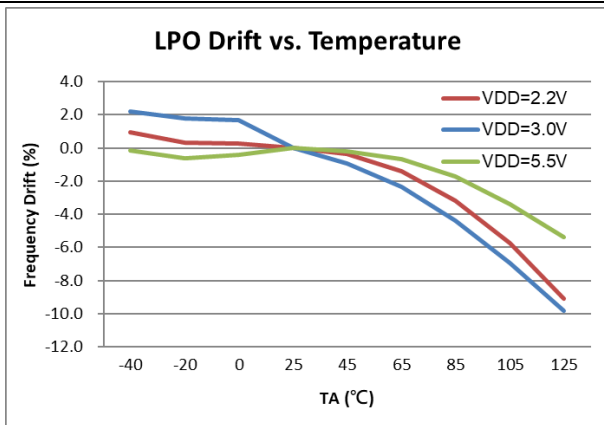


Figure 6.2-3 LPO vs. Temperature

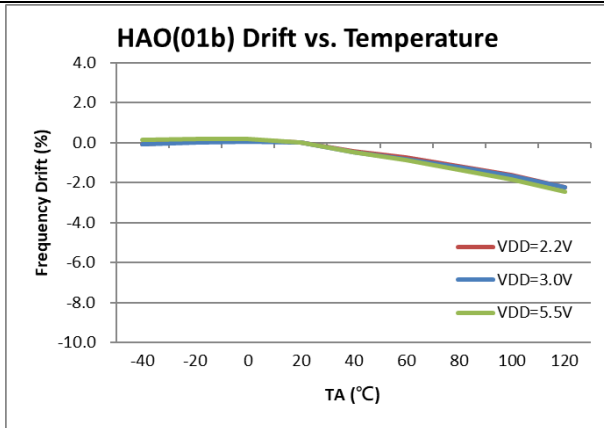


Figure 6.2-4 HAO(4.9152MHz) vs. Temperature

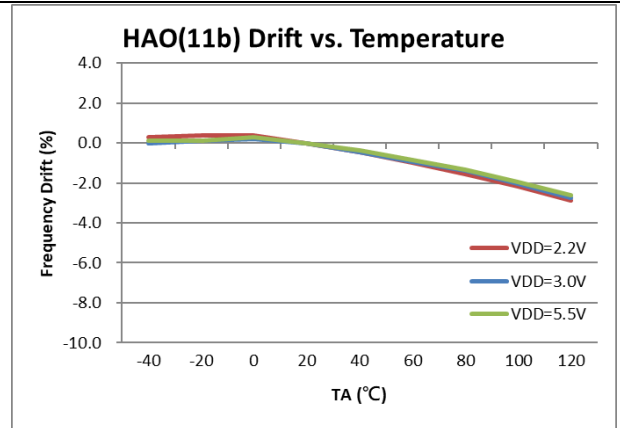


Figure 6.2-5 HAO(9.8304MHz) vs. Temperature

6.3. Supply current into VDD excluding peripherals current

$T_A = 25^\circ\text{C}, V_{DD} = 3.0\text{V}, \text{OSC_LPO} = 14.5\text{KHz}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	OSC_CY = off, OSC_HAO = 9.8304MHz, CPU_CK = 9.8304MHz		600	1000	μA
I_{AM2}	Active mode 2	OSC_CY = off, OSC_HAO = 4.9152MHz, CPU_CK = 4.9152MHz		320	650	μA
I_{LP1}	Low Power 1	OSC_CY = off, OSC_HAO = off, CPU_CK = LPO,		2	5	μA
I_{LP2}	Low Power 2	OSC_CY = off, OSC_HAO = off, CPU_CK = LPO, Idle state		1.0	2.5	μA
I_{LP3}	Low Power 3	OSC_CY = off, OSC_HAO = off, CPU_CK = off, Sleep state		0.25	1.0	μA
I_{LP4}	Low Power 4	OSC_CY = 32768Hz, OSC_HAO = off, CPU_CK = 32768Hz, Idle state		1.8	3.6	μA

OSC_CY : External Oscillator frequency.
OSC_HAO : Internal High Accuracy Oscillator frequency.
CPU_CK : CPU core work frequency.

$T_A = 25^\circ\text{C}, V_{DD} = 5.5\text{V}, \text{OSC_LPO} = 14.5\text{KHz}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AM1}	Active mode 1	OSC_CY = off, OSC_HAO = 9.8304MHz, CPU_CK = 9.8304MHz		1200	1800	μA
I_{AM2}	Active mode 2	OSC_CY = off, OSC_HAO = 4.9152MHz, CPU_CK = 4.9152MHz		720	1200	μA
I_{LP1}	Low Power 1	OSC_CY = off, OSC_HAO = off, CPU_CK = LPO,		4	10	μA
I_{LP2}	Low Power 2	OSC_CY = off, OSC_HAO = off, CPU_CK = LPO, Idle state		2.5	5	μA
I_{LP3}	Low Power 3	OSC_CY = off, OSC_HAO = off, CPU_CK = off, Sleep state		0.4	2	μA

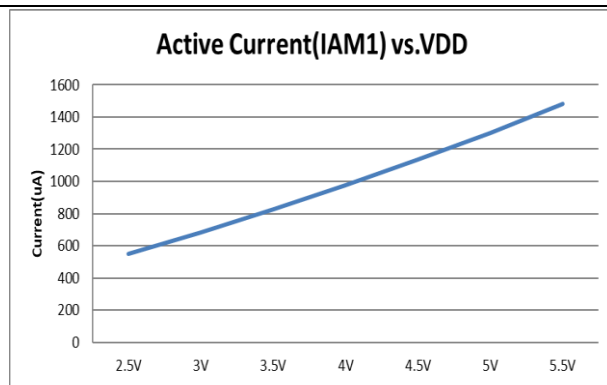


Figure 6.3-1 I_{AM1} vs. VDD

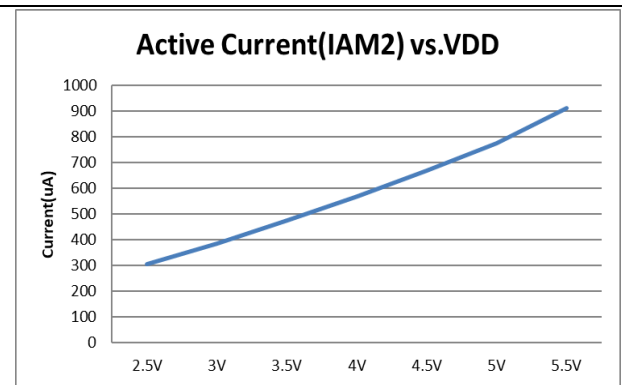


Figure 6.3-2 I_{AM2} vs. VDD

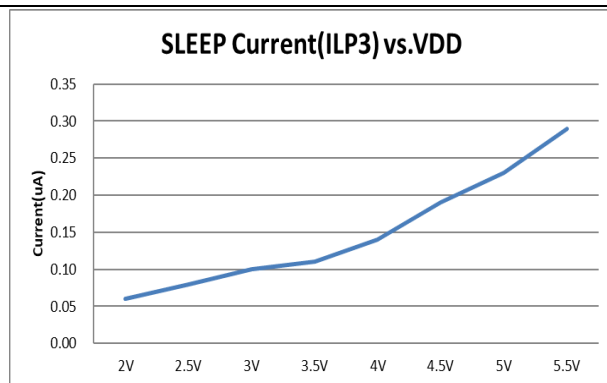


Figure 6.3-3 I_{AM3} vs. VDD

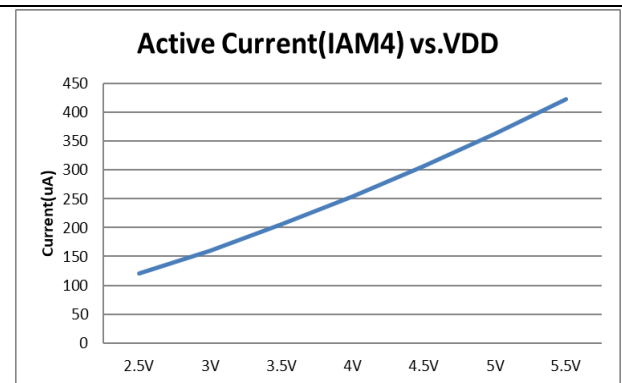


Figure 6.3-4 I_{AM4} vs. VDD

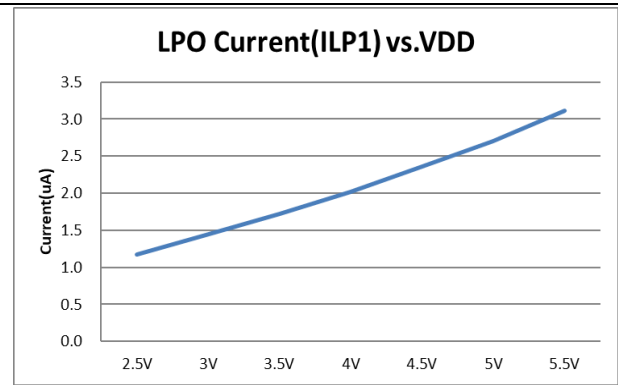


Figure 6.3-5 I_{LP1} vs. VDD

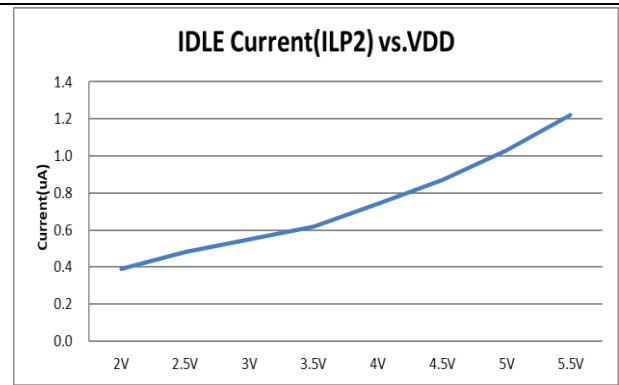


Figure 6.3-6 I_{LP2} vs. VDD

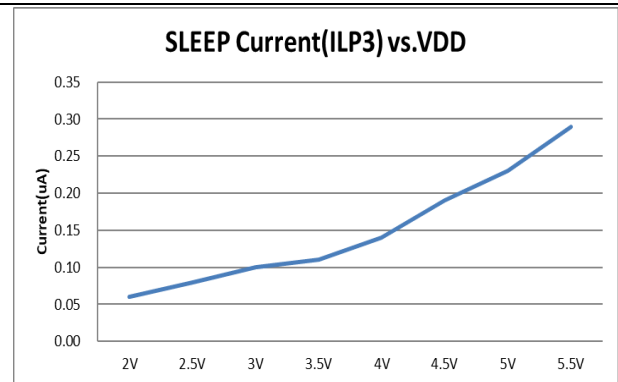


Figure 6.3-7 I_{LP3} vs. VDD

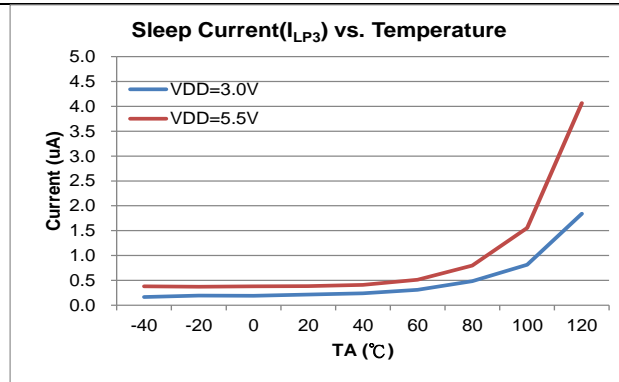
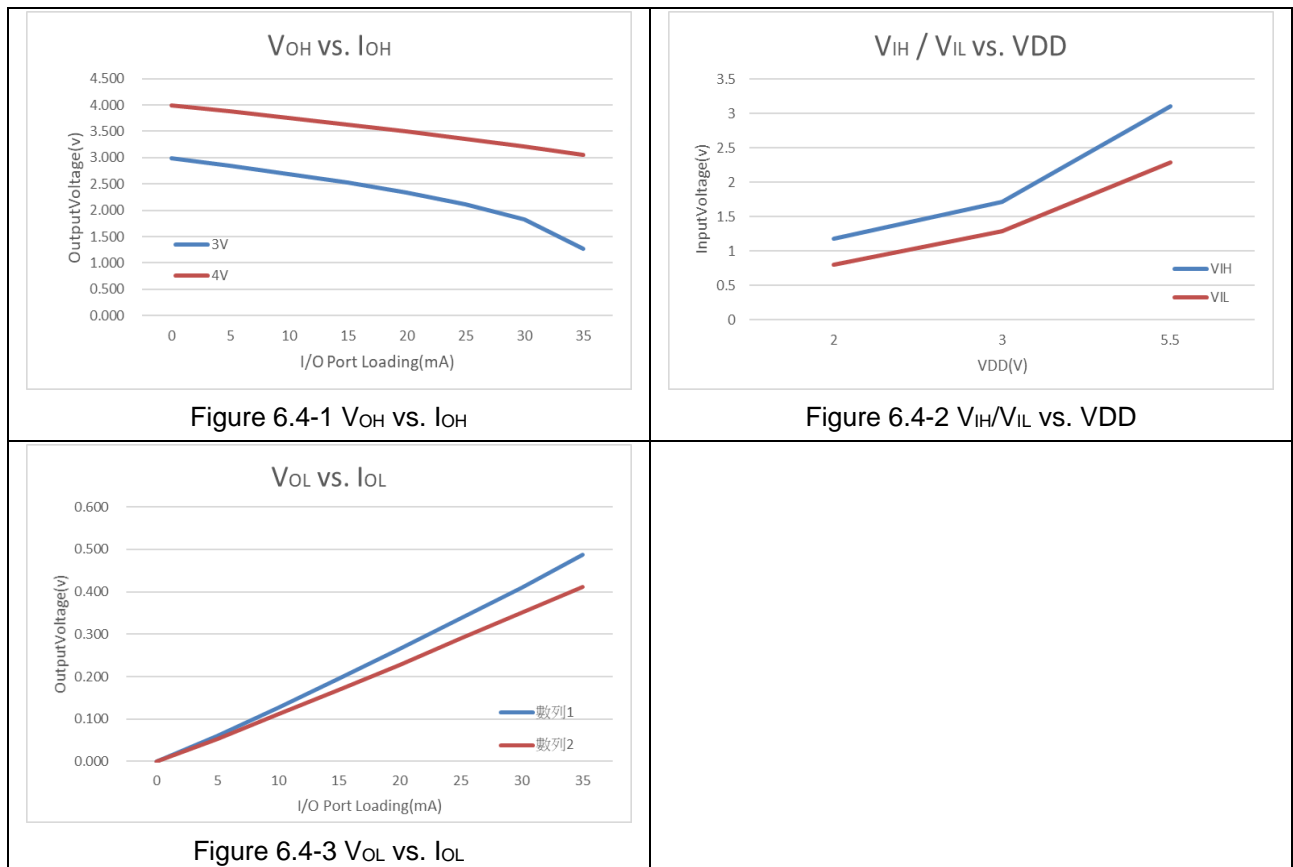


Figure 6.3-8 I_{LP3} vs. Temperature

6.4. Port 1,2,3,6,8

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Input voltage and Schmitt trigger and leakage current and timing						
V_{IH}	High-Level input voltage				$0.7 \cdot V_{DD}$	V
V_{IL}	Low-Level input voltage		$0.3 \cdot V_{DD}$			
V_{hys}	Input Voltage hysteresis($V_{IH} - V_{IL}$)			$0.3 \cdot V_{DD}$		V
I_{LKG}	Leakage Current				0.1	μA
R_{PU}	Port pull high resistance			60		$\text{k}\Omega$
Output voltage and current and frequency						
V_{OH}	High-level output voltage	$V_{DD}=3\text{V}$, $I_{OH}=-10\text{mA}$,	$V_{DD} - 0.4$		V	
		$V_{DD}=5\text{V}$, $I_{OH}=-15\text{mA}$,	$V_{DD} - 0.4$			
V_{OL}	Low-level output voltage	$V_{DD}=3\text{V}$, $I_{OL}=10\text{mA}$	$V_{SS} + 0.4$			
		$V_{DD}=5\text{V}$, $I_{OL}=15\text{mA}$	$V_{SS} + 0.4$			



6.5. Reset(Brownout)

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit	
BOR1	Pulse length needed to accepted reset internally, t_{d-LVR1}		2			uS	
	V_{DD} Start Voltage to accepted reset internally (L \rightarrow H), V_{HYS1}		1.0	1.35	1.65	V	
	BOR1 current, I_{BOR1}		0.2			0.5	uA
	Temperature Drift		5			%	
BOR2	Pulse length needed to accepted reset internally, t_{d-LVR2}		2			uS	
	V_{DD} Start Voltage to accepted reset internally (L \rightarrow H), V_{HYS2} , and BOR_TH[2:0]:	000b	-8%	1.73	+8%	V	
		001b	-8%	2.0	+8%		
		010b	-8%	2.22	+8%		
		011b	-8%	2.5	+8%		
		100b	-8%	2.72	+8%		
		101b	-8%	3.0	+8%		
		110b	-10%	3.63	+10%		
		111b	-10%	4.0	+10%		
	V_{DD} Start Voltage to accepted reset internally (H \rightarrow L), V_{LVR2} , and BOR_TH[2:0]:	000b	-8%	1.67	+8%	V	
		001b	-8%	1.96	+8%		
		010b	-8%	2.17	+8%		
		011b	-8%	2.44	+8%		
		100b	-8%	2.69	+8%		
		101b	-8%	2.96	+8%		
		110b	-10%	3.58	+10%		
		111b	-10%	3.94	+10%		
	Hysteresis, $V_{HYS2-LVR2}$		25	60	90	mV	
BOR2 current, I_{BOR2}		10			15	uA	
Temperature Drift		3			5	%	
RST	Pulse length needed as RST/VPP pin to accepted reset internally, t_{d-RST}		2			uS	
	Input Voltage to accepted reset voltage		1.1			V	
	Reset release voltage		2			V	
BOR1/BOR2 : Brownout Reset 1/2 LVR : Low Voltage Reset of BOR RST : External Reset pin							

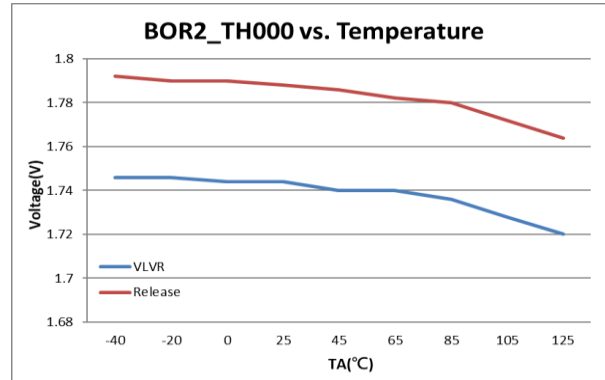


Figure 6.5-1 BOR vs. Temperature

6.6. Power System

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
VDDA	VDDA operation current, I_{VDDA}	$I_L = 0\text{mA}$	LDOC[2:0]=000b	20			μA
	Select VDDA output voltage	$I_L = 0.1\text{mA}$, $V_{DD} \geq$ $V_{DDA} + 0.25\text{V}$	LDOC [2:0]=000b	-5%	+5%	2.4	V
			LDOC [2:0]=001b			2.6	V
			LDOC [2:0]=010b			2.9	V
			LDOC [2:0]=011b			3.3	V
			LDOC [2:0]=100b			3.6	V
			LDOC [2:0]=101b			4.0	V
			LDOC [2:0]=110b			4.5	V
	Dropout voltage	$I_L = 10\text{mA}$	LDOC [2:0]=000b		250		mV
Temperature drift	LDOC [2:0]=000b $I_L = 0.1\text{mA}$	$T_A = -40^\circ\text{C} \sim 85^\circ\text{C}$	50			PPM/ $^\circ\text{C}$	
V_{DD} Voltage drift	LDOC [2:0]=000b	$V_{DD} = 2.2\text{V} \sim 5.5\text{V}$	± 0.2			%/V	
AGND	AGND operation current, I_{Agnd}	SAGND \neq 000b	$I_L = 0\text{mA}$		400		μA
	Output voltage, V_{Agnd}	SAGND=001b	$I_L = 0\mu\text{A}$	-5%	$V_{DDA} * 0.3$	-5%	V
		SAGND=010b	$I_L = 0\mu\text{A}$	-5%	$V_{DDA} * 0.1$	-5%	V
		SAGND=011b	$I_L = 0\mu\text{A}$	-5%	$V_{DDA} * 0.5$	-5%	V
		SAGND=100b	$I_L = 0\mu\text{A}$	-5%	$V_{DDA} * 0.4$	-5%	V
REFO	REFO operation current, I_{AREFO}		$I_L = 0\mu\text{A}$		260		μA
	$V(\text{REFO}, V_{SS})$		$I_L = 0\mu\text{A}$	-3%	1.2	-3%	V
	Temperature drift		$T_A = -40^\circ\text{C} \sim 85^\circ\text{C}$		100		ppm/ $^\circ\text{C}$
	RMS Noise				60		μVrms

VDDA : Adjust Voltage Regulator,

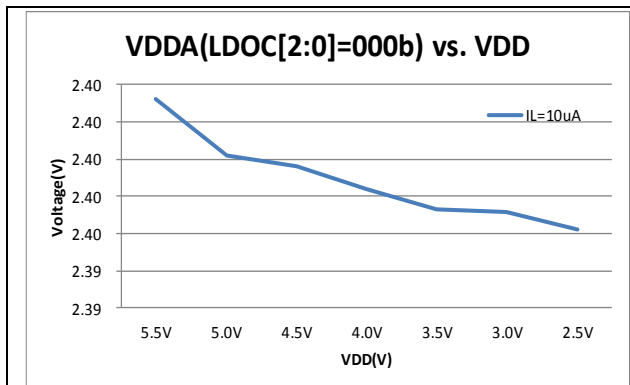


Figure 6.6-1 VDDA(000b) vs. VDD

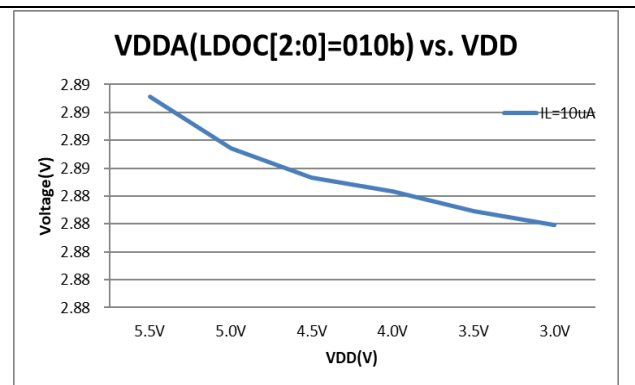


Figure 6.6-2 VDDA(010b) vs. VDD

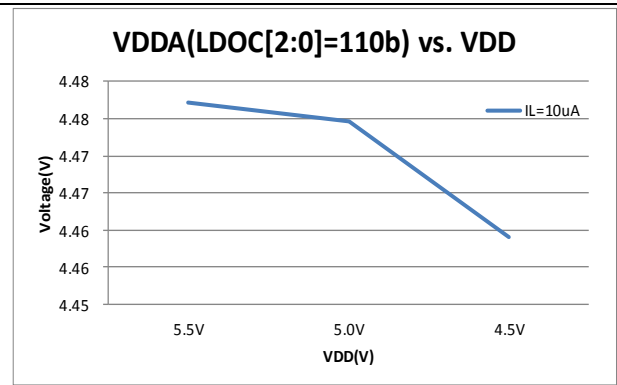


Figure 6.6-3 VDDA(110b) vs. VDD

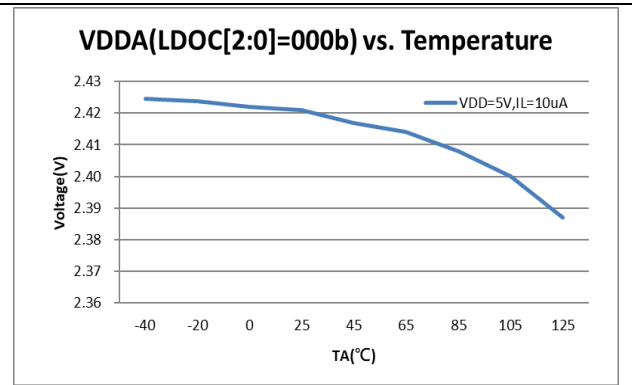


Figure 6.6-4 VDDA(000b) vs. Temperature

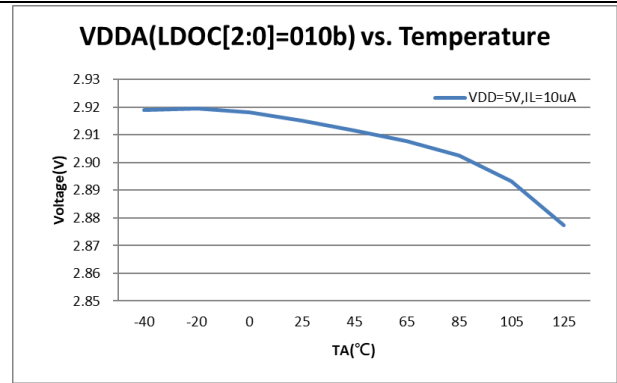


Figure 6.6-5 VDDA(010b) vs. Temperature

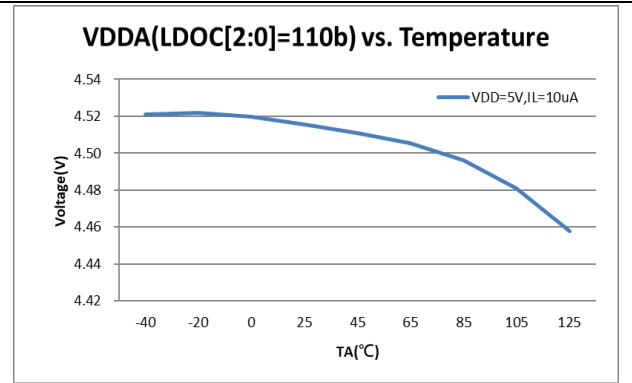


Figure 6.6-6 VDDA(110b) vs. Temperature

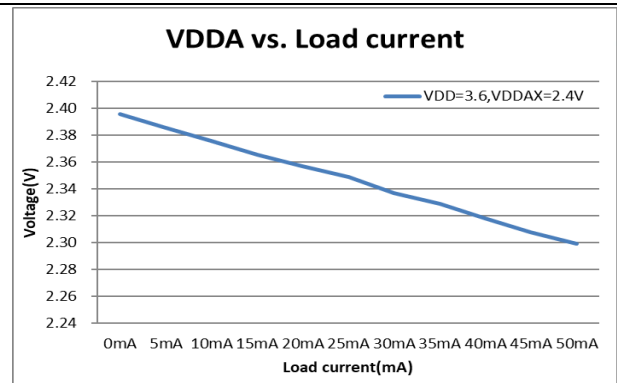


Figure 6.6-7 VDDA vs. Load current

6.7. Multi-Function Comparator

TA = 25°C, VDD = 3.0V, unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
IMC	Operation supply current	ENCMP[0]=1, CMPHS[0]=1b		5		uA
	Low Power Mode	ENCMP[0]=1, CMPHS [0]=0b		1		
VIC	Common-mode input voltage		0		VDD-1	V
VOS	Offset voltage		-5		5	mV
Vhys	Input hysteresis		0	0.7	1.5	mV
Vaccy	Reference Voltage	ENLDO[0]=1b, CPPS[1:0]=11b,	1.15	1.2	1.25	V
	Temperature Drift	VRSEL[0]=1b		50		ppm/°C
	VDD Voltage drift			±0.2		%/V
IR	Multi-node resistor current	CPRL[0]=0b		10		uA
		CPRL[0]=1b		30		
	ENLDO[0]=1b, CPPS[1:0]=11b, CPRH [1:0]=01b, CPRL[0]=0b.	CPDA[4:0]=00011b	-5%	5%	3.89	V
		CPDA[4:0]=00100b			3.73	
		CPDA[4:0]=00101b			3.58	
		CPDA[4:0]=00110b			3.44	
		CPDA[4:0]=00111b			3.31	
		CPDA[4:0]=01000b			3.19	
		CPDA[4:0]=01001b			3.08	
		CPDA[4:0]=01010b			2.98	
		CPDA[4:0]=01011b			2.88	
		CPDA[4:0]=01100b			2.79	
		CPDA[4:0]=01101b			2.71	
		CPDA[4:0]=01110b			2.63	
		CPDA[4:0]=01111b			2.55	
		CPDA[4:0]=10000b			2.48	
		CPDA[4:0]=10001b			2.42	
		CPDA[4:0]=10010b			2.35	
		CPDA[4:0]=10011b			2.29	
		CPDA[4:0]=10100b			2.24	
CPDA[4:0]=10101b	2.18					
CPDA[4:0]=10110b	2.13					
CPDA[4:0]=10111b	2.08					
CPDA[4:0]=11000b	2.03					
CPDA[4:0]=11001b	1.99					
CPDA[4:0]=11010b	1.94					

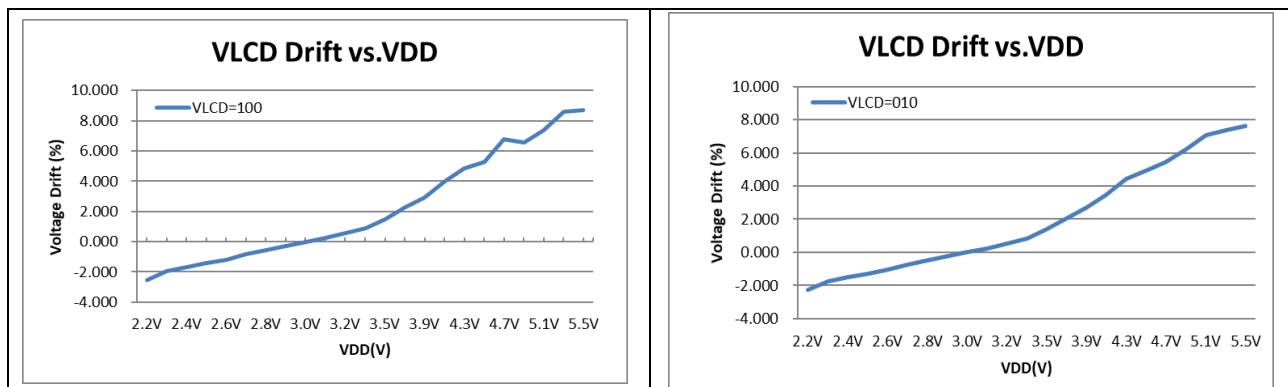
		CPDA[4:0]=11011b		1.90		
		CPDA[4:0]=11100b		1.86		
		CPDA[4:0]=11101b		1.82		
CPDA[4:0]=00000b~00010b, and 11110b~11111b (reserved)						

LVD : Low Voltage Detect.

6.8. LCD

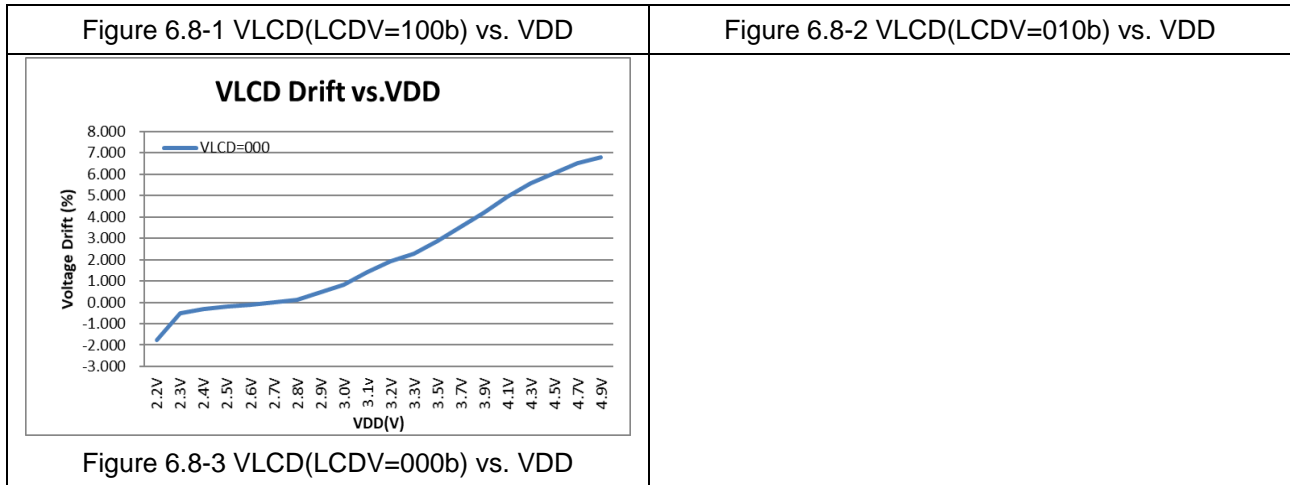
$T_A = 25^{\circ}\text{C}$, $V_{DD} = 3.3\text{V}$, $C_{VLCD} = 4.7\mu\text{F}$, unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
I_{LCD}	Operation supply current with output buffer.(all segment turn on, No load)	ENLCP[0]=1 $V_{DD} = 3.0\text{V}$		8		μA	
VLCD	Supply Voltage at VLCD pin	ENLCP [0]=0	2.4		5	V	
	Embedded Charge Pump output voltage at VLCD pin	$V_{DD} = 3.3\text{V}$, ENLCP [0]=1, $C_{VLCD} = 4.7\mu\text{F}$	LCDV[2:0]=111b	-10%	2.45	+10%	V
		LCDV[2:0]=110b	-10%	2.70	+10%		
		LCDV[2:0]=101b	-10%	2.85	+10%		
		LCDV[2:0]=100b	-10%	3.10	+10%		
		LCDV[2:0]=011b	-10%	3.30	+10%		
		LCDV[2:0]=010b	-10%	4.10	+10%		
		LCDV[2:0]=001b ($V_{DD} > 2.4\text{V}$ mode)	-10%	4.55	+10%		
LCDV[2:0]=000b ($V_{DD} > 2.75\text{V}$)	-10%	5.1	+10%				
	VDD Voltage drift	ENLCP [0]=1, $C_{VLCD} = 4.7\mu\text{F}$, LCDV[2:0]>010b, $V_{DD} = 2.2\text{V} \sim 5.5\text{V}$; LCDV[2:0]=001b, $V_{DD} > 2.4\text{V}$; LCDV[2:0]=000b, $V_{DD} > 2.75\text{V}$;		4		%/V	
Z_{LCD}	Output impedance with LCD buffer	$f_{LCD} = 128\text{Hz}$, $V_{LCD} = 3.05\text{V}$		10		$\text{k}\Omega$	



HY17P60B

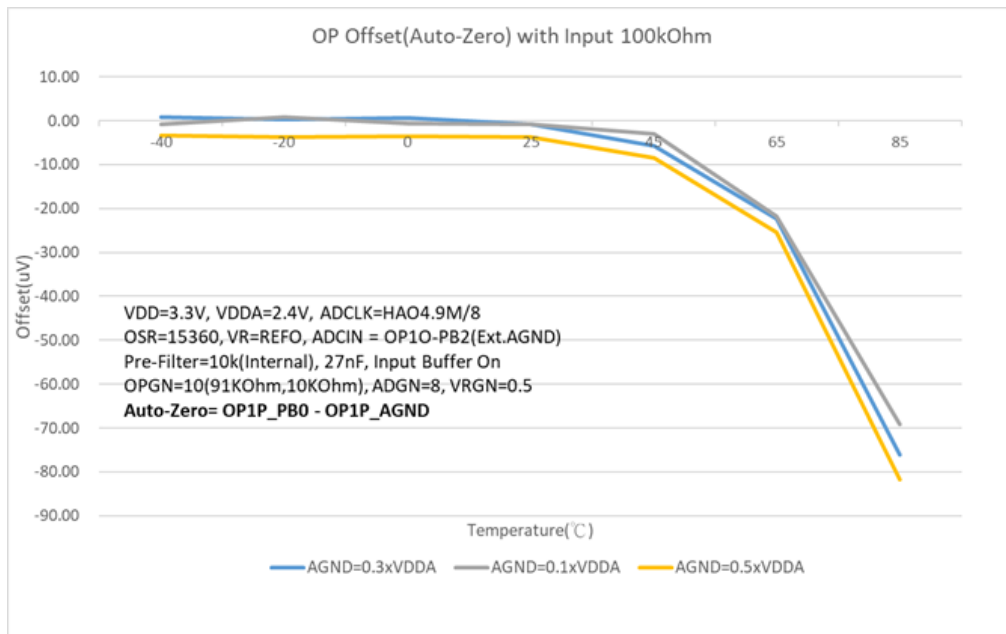
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6.9. OPAMP

TA = 25°C, VDD = 3.3V, VDDA=2.4V, AGND=0.3VDDA, Input buffer on unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{os-op}	Input offset voltage	OP Gain=10, ADGN=8, VRGN=0.5 Pre-Filter=10K(Inside) / 27nF(Outside)			800	uV
	Input offset voltage with Auto-Zero	Auto-Zero(OP1P_PB0-OP1P_AGND) OP Gain=10, ADGN=8, VRGN=0.5 Pre-Filter=10K(Inside) / 27nF(Outside)		-2		uV
V_{os-td}	OP Input offset temperature drift	with Auto-Zero, TA=-40°C ~ 85°C		0.64		uV/°C
CMVR	Common-mode voltage input range		VSS+0.1		VDDA - 1.1	V



6.10. Σ ADC, Power Supply and recommended operating conditions

TA = 25°C, VDD = 3.0V, VDDA=2.4V, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
V _{SD18}	Supply Voltage at VDDA	ENLDO[0]=0		2.4		5.5	V
I _{ΣADC}	Operation supply current	Input gain =1, input buffer on			254		uA
f _{ΣADC}	Modulator sample frequency, ADC_CK				1		MHz
	Over Sample Ratio, OSR			32		61440	
Eos	Input offset voltage	Chopper on OSR=61440	Input gain=1, reference gain=1		1		uV
Vrms	Input RMS Noise	Chopper on, OSR=61440, input gain=1 reference gain=1			3.5		uV
		Chopper off, OSR=32, input gain=1 reference gain=1			350		uV
NM	Normal Rejection ratio	Chopper On OSR=61440	Input gain=1, reference gain=1. Vin=200mVrms 50/60Hz		60		dB
AC _{bw}	AC Measurement Bandwidth	OSR=32, LPFBW=1024 Without Voltage Divider	0.5% error	20		4k	Hz
			3dB				
			Square wave, 0.5% error			0.3k	
			Triangle wave, 0.5% error				

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		A/D Clock=1MHz	<i>ENOB(RMS) with OSR/GAIN at A/D Clock=0.5MHz, VDD=3.3V, VDDA=2.4V, AGND=0.3VDDA, VREF=1.2, Vin=Ext.Short, Chopper Off;</i>						
Max. Vin(mV) =0.9*VR EF ⁽¹⁾	OSR	32	64	128	256	7680	15360	30720	61140
	Output rate(Hz)	31250	7813	3906	1953	65	33	16	8
	Gain								
± 2160	0.5	12.63	14.09	14.78	15.3	17.96	18.39	18.7	19
± 1080	1	12.77	14.09	14.66	15.13	17.9	18.24	18.57	18.87
± 540	2	12.66	14.01	14.62	15.13	17.68	18.01	18.29	18.41
± 270	4	12.53	13.81	14.53	15.12	17.28	17.7	17.57	18.06
± 135	8	12.29	13.46	14.17	14.77	16.78	16.8	16.97	16.98

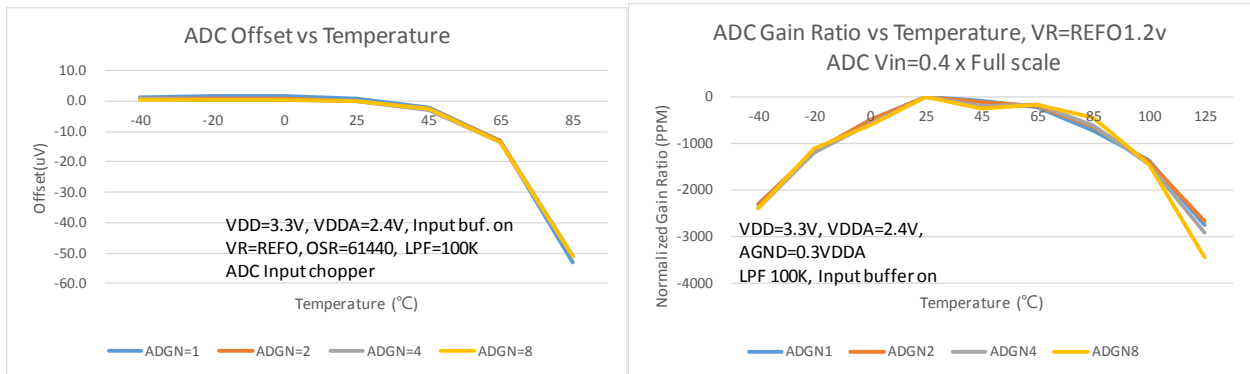
		A/D Clock=1MHz	<i>RMS Noise(uV) with OSR/GAIN at A/D Clock=0.5MHz, VDD=3.3V, VDDA=2.4V, AGND=0.3VDDA, VREF=1.2, Vin=Ext.Short, Chopper Off;</i>						
Max. Vin(mV) =0.9*VR EF ⁽¹⁾	OSR	32	64	128	256	7680	15360	30720	61140
	Output rate(Hz)	31250	7813	3906	1953	65	33	16	8
	Gain								
± 2160	0.5	759.55	276.19	170.49	118.99	18.77	13.94	11.24	9.16
± 1080	1	344.59	137.19	92.75	66.86	9.80	7.75	6.17	5.02
± 540	2	185.38	72.84	47.80	33.52	5.72	4.54	3.75	3.44
± 270	4	101.38	41.88	25.35	16.90	3.77	2.82	3.08	2.19
± 135	8	59.82	26.70	16.28	10.74	2.66	2.62	2.34	2.33

Table 6.10-1(a) SD18, Chopper Off, ENOB and RMS Noise Table

		<i>ENOB(RMS) with OSR/GAIN at A/D Clock=0.5MHz, VDD=3.3V, VDDA=2.4V, AGND=0.3VDDA, VREF=1.2, Vin=Ext.Short, Chopper On ;</i>							
Max. Vin(mV) =0.9*VR EF ⁽¹⁾	OSR	64	128	256	7680	15360	30720	61140	
	Output rate(Hz)	3906	1953	977	33	16	8	4	
	Gain								
± 2160	0.5	14.71	15.27	15.88	18.5	18.85	19.2	19.47	
± 1080	1	14.74	15.32	15.79	18.42	18.83	19.14	19.45	
± 540	2	14.6	15.13	15.57	18.36	18.75	19.03	19.32	
± 270	4	14.48	15.08	15.76	18.09	18.43	18.74	18.86	
± 135	8	14.05	14.77	15.33	17.56	17.9	18.03	18.18	

		<i>RMS Noise(uV) with OSR/GAIN at A/D Clock=0.5MHz, VDD=3.3V, VDDA=2.4V, AGND=0.3VDDA, VREF=1.2, Vin=Ext.Short, Chopper On ;</i>							
Max. Vin(mV) =0.9*VR EF ⁽¹⁾	OSR	64	128	256	7680	15360	30720	61140	
	Output rate(Hz)	3906	1953	977	33	16	8	4	
	Gain								
± 2160	0.5	179.26	121.63	79.58	12.92	10.16	7.97	6.61	
± 1080	1	87.63	58.69	42.32	6.85	5.14	4.17	3.34	
± 540	2	48.37	33.37	24.68	3.56	2.73	2.24	1.83	
± 270	4	26.26	17.36	10.85	2.15	1.70	1.37	1.26	
± 135	8	17.66	10.71	7.31	1.55	1.23	1.12	1.01	

Table 6.10-1(b) SD18, Chopper On, ENOB and RMS Noise Table



6.10.1. Σ ADC, Temperature Sensor

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $V_{DDA} = 2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
TC_S	Sensor temperature drift			173		$\mu\text{V}/^\circ\text{C}$
KT	Absolute Temperature Scale 0°K			284		$^\circ\text{C}$
TC_{ERR}	One point calibrate error temperature	Calibration at 25°C of -40°C – 85°C		± 2		$^\circ\text{C}$

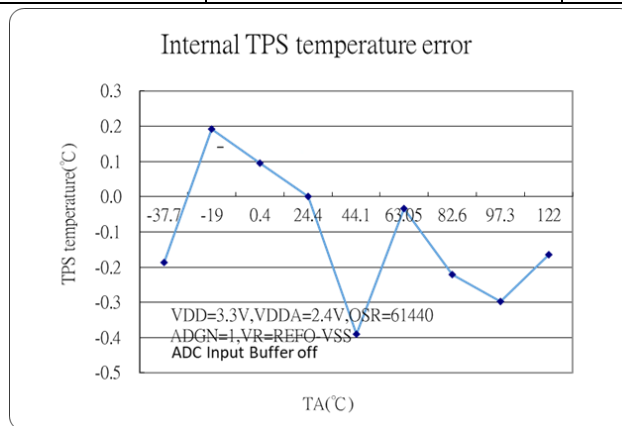


Figure 6.10-2 ADC Temperature Error

6.11. Analog input and switch performance

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $V_{DDA} = 2.4\text{V}$, $AGND = 0.5V_{DDA}$ unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{AL}	Analog Input Leakage Current	$AGND = 0.5V_{DDA}$		10	100	pA
		$AGND = 0.3V_{DDA}$		10	100	
		$AGND = 0.1V_{DDA}$		100	500	

6.12. Build-In EPROM(BIE)

$T_A = 25^\circ\text{C}, V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{BIE}	Supply Voltage at VPP PIN			8.5	8.75	V
I_{BIE}	Operation supply current			3		mA
V_{SS}	Supply Voltage			0		V

When connecting to the external V_{BIE} power source to program the BIE block, users can use the instruction to program the words one by one into the BIE block.

6.13. Build-In EPROM(BIE) Low voltage control circuit

$T_A = 25^\circ\text{C}, V_{DD} = 3.05\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	unit
T_O	Operation temperature range		0	25	40	$^\circ\text{C}$
V_{DD}	Operation supply Voltage		2.75		5.5	V
V_{SS}	Supply Voltage			0		V

When the 2.75V low voltage programming control circuit is activated, users can program the BIE block without connecting to the external V_{BIE} power source.

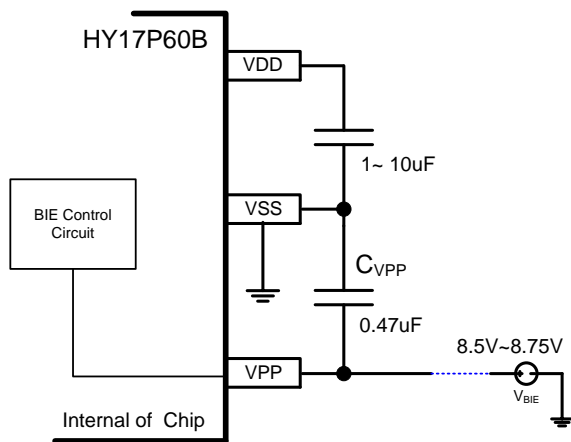


图 6.13-1 HY17P60B 外灌 VPP 烧录 BIE 应用方块图

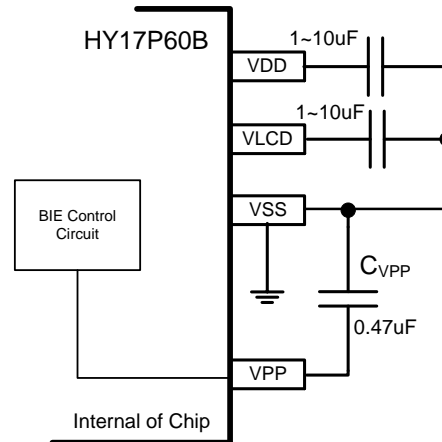


图 6.13-2 HY17P60B 低压烧录 BIE 应用方块图

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7. 订货信息

下单品名 ¹	封装型式	引脚数	封装型式		程序代码	出货包装形式	个装数量	材料组成	MSL ³
			描述方式	编号 ²	编号 ²				
HY17P60B-D000	Die	-	D	000	000	Tray	200	Green ⁴	-
HY17P60B-L064	LQFP	64	L	064	000	Tray	250	Green ⁴	MSL-3
HY17P60B-NS32	QFN	32	N	S32	000	Tape & Reel	3000	Green ⁴	MSL-3

¹ 产品名称 品名封装型式描述方式 装型程序代码编号 (空白片 / 标准品 / 代客烧录码)

例如：您的 HY17P60B 程序代码编号为 001，且需要的产品是裸片出货。则下单品名为 HY17P60B-D000-001。

例如：您的需求是 HY17P60B 不带程序代码的空白片且需要的产品是裸片出货。则下单品名为 HY17P60B-D000。

例如：您的需求是 HY17P60B 不带程序代码的空白片且需要的产品是封装片 LQFP64 出货，则下单品名为 HY17P60B-L064，且需以 Tray 出货，则除下单品名外，请特别注明出货包装形式为 Tray。

例如：您的 HY17P60B 程序代码编号为 002，而需求的产品是封装片 LQFP64 出货，则下单品名为 HY17P60B-L064-002，且需以 Tray 出货，则除下单品名外，请特别注明出货包装形式为 Tray。

² 程序代码编号

“001”~“999”为标准品或代客申请的程序代码编号，而空白芯片不带此码。

³ MSL:

湿度敏感性等级系依据 IPC/JEDEC J-STD-020 的规范加以试验分级，并参考 IPC/JEDEC J-STD-033 的标准处理、包装、运输与使用。

⁴ Green (RoHS & no Cl/Br):

HYCON 产品皆为 Green Product，符合 RoHS 指令，REACH 高关注物质(SVHC)以及无卤素规定 (Br<900ppm or Cl<900ppm or (Br+Cl)<1500ppm)。

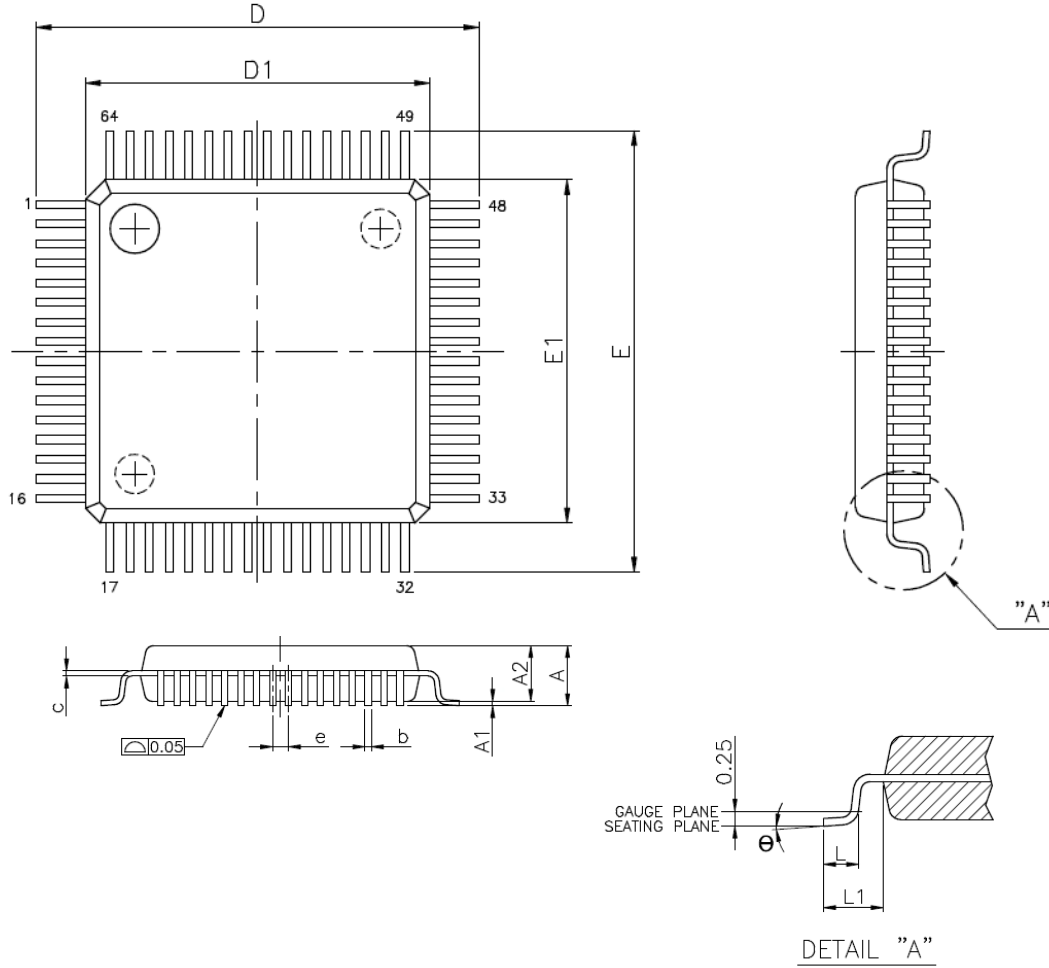
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8. 封装型式信息

8.1. LQFP64(L064)

8.1.1. Package Dimensions LQFP64(7x7)



SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
b	0.13	0.18	0.23
c	0.09	—	0.20
D	9.00 BSC		
D1	7.00 BSC		
e	0.40 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
θ	0°	3.5°	7°

Note:

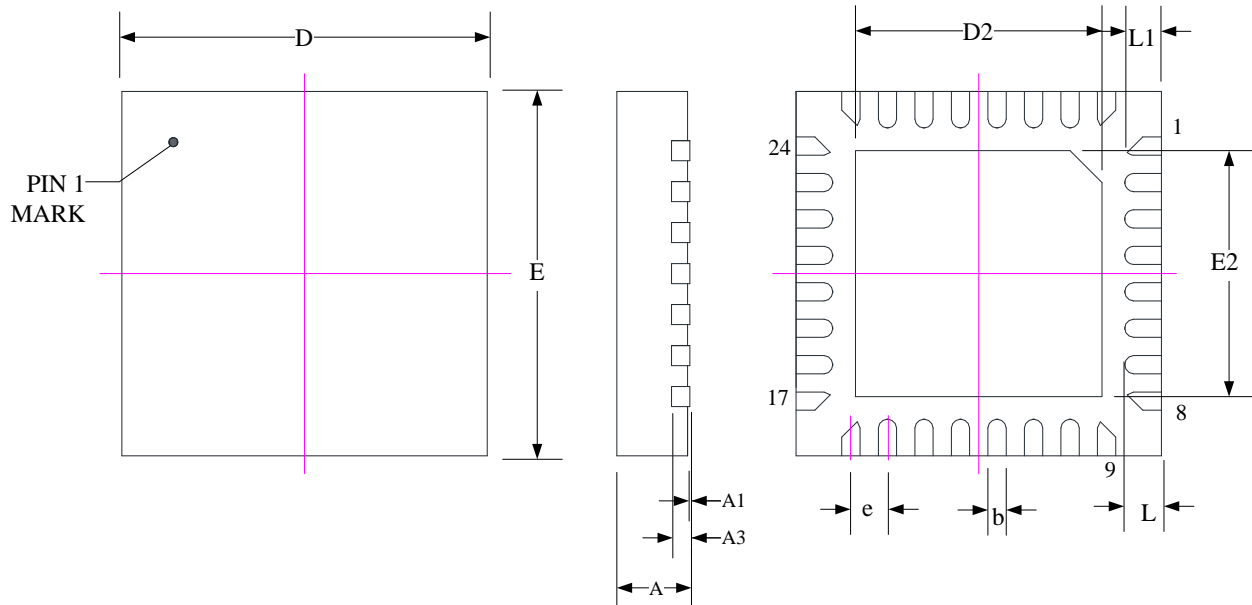
1. All dimensions refer to JEDEC OUTLINE MS-026.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

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8.2. QFN32(NS32)

8.2.1. Package Dimensions QFN32(4x4)



SYMBOLS	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.15	0.20	0.25
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	2.65	2.70	2.75
E2	2.65	2.70	2.75
L	0.35	0.40	0.45
L1	0.332	0.382	0.432
e	0.40 BASIC		

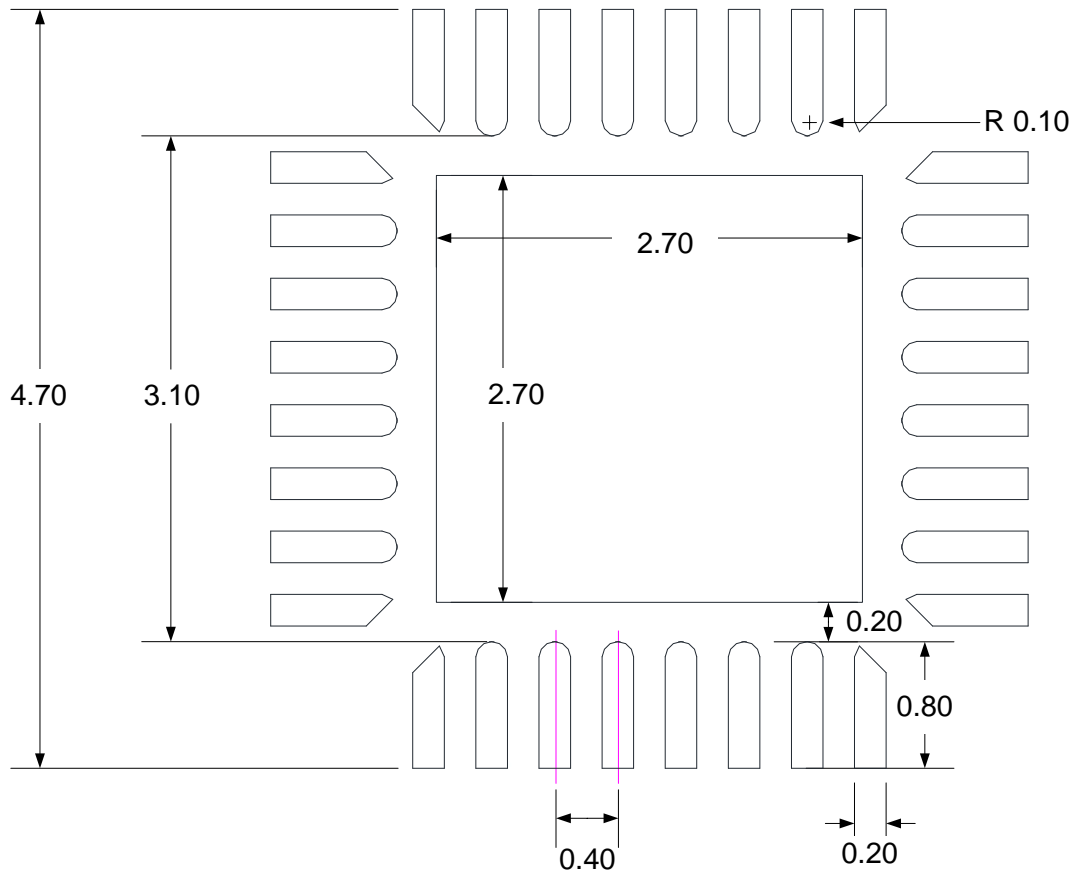
Note:

1. All dimensions refer to JEDEC OUTLINE MO-220.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

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8.2.2. Land Pattern Design Recommendations



Note:

1. Publication IPC-7351 is recommended for alternate designs.
2. https://www.hycontek.com/wp-content/uploads/QFN_DFN_PCB.pdf
3. Unit: mm.

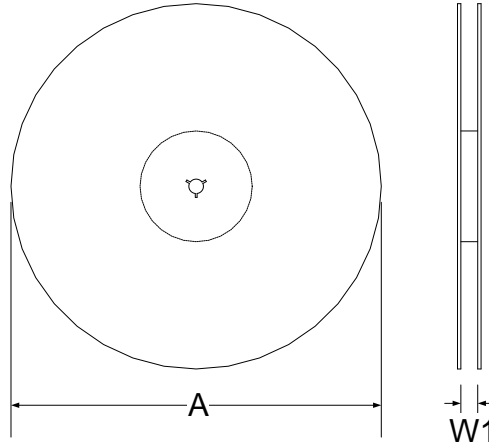
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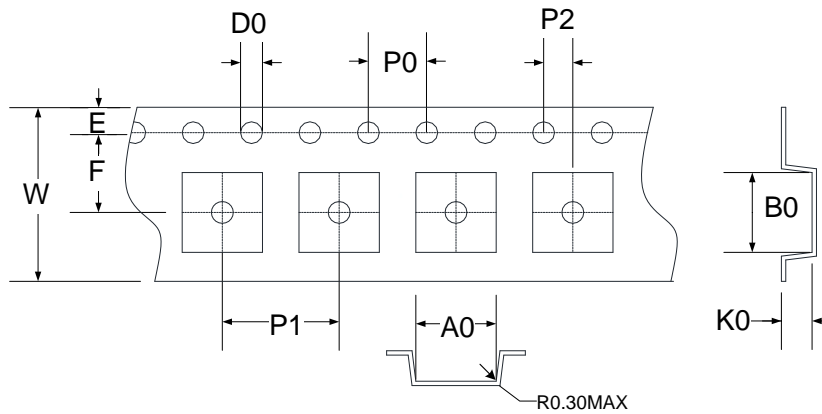
8.2.3. Tape & Reel Information

8.2.3.1. Reel Dimensions

Unit: mm



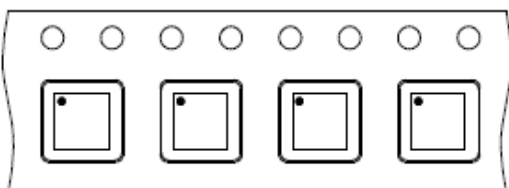
8.2.3.2. Carrier Tape Dimensions



SYMBOLS	Reel Dimensions		Carrier Tape Dimensions										
	A	W1	A0	B0	K0	P0	P1	P2	E	F	D0	W	
Spec.	330	12.5	4.35	4.35	1.10	4.00	8.00	2.00	1.75	5.50	1.50	12.00	
Tolerance	+6/-3	+1.5/-0	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.10	±0.05	+0.1/-0	±0.30

Note: 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.

8.2.3.3. Pin1 direction



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9. 修订纪录

以下描述本档差异较大的地方，而标点符号与字形的改变不在此描述范围。

文件版次	页次	日期	摘要
V01	All	2021/11/29	初版发行